

High Data Rate 60 GHz CMOS Transceiver Design

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Nov.12. 2015.

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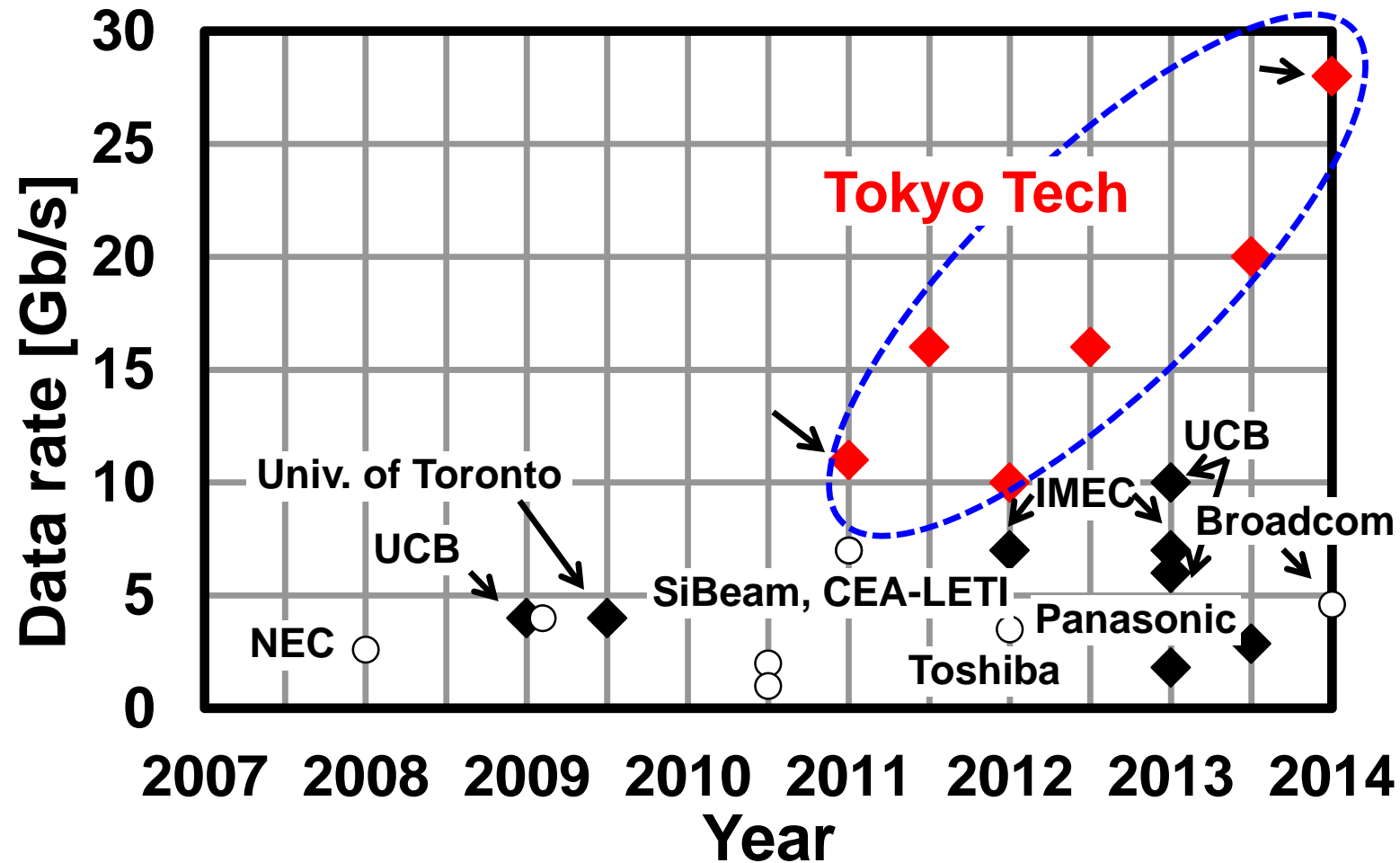
Background and Motivation

Progress of data rate in 60 GHz band

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Our lab. is developing high data rate wireless transceivers.
28 Gbps has been attained.



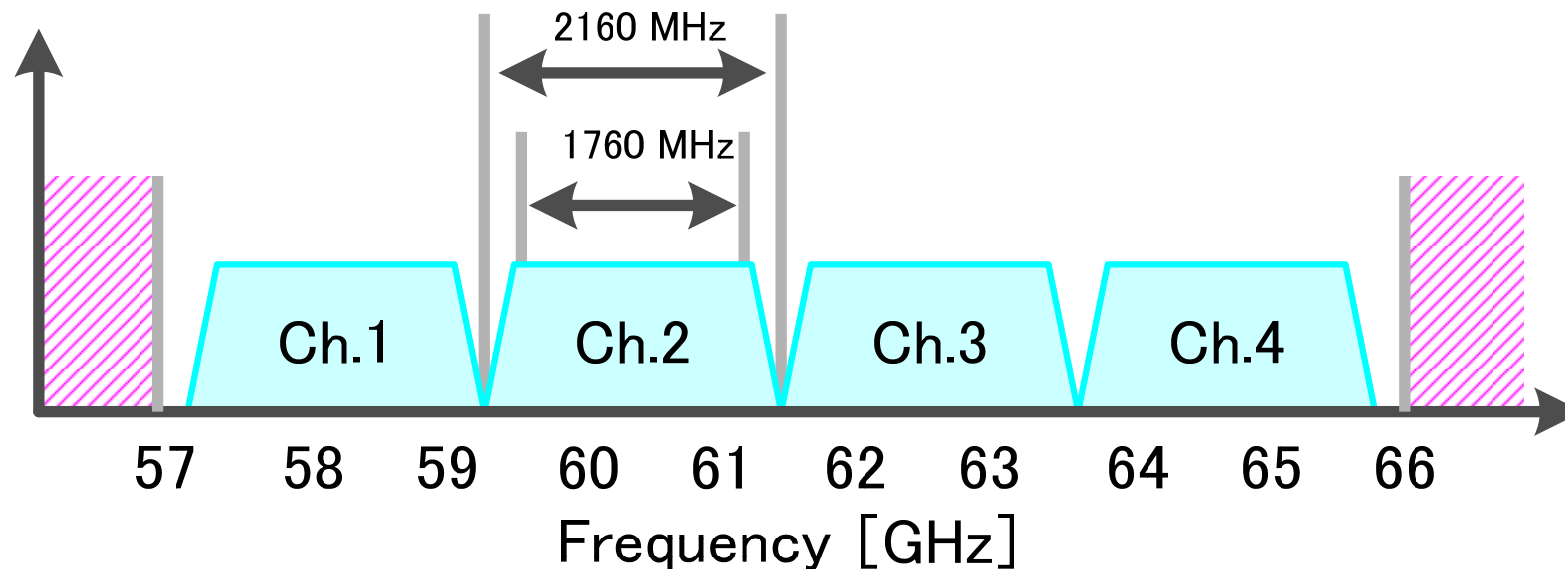
60GHz bandwidth allocation on IEEE 802.ad

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Totally 9 GHz can be used.

The use of high # of bit can attain ultra-high data rate com.

	BPSK	QPSK	16QAM	64QAM
1ch	1.76	3.52	7.04	10.56
2ch	3.52	7.04	14.08	21.12
3ch	5.28	10.56	21.12	31.68
4ch	7.04	14.08	28.16	42.24

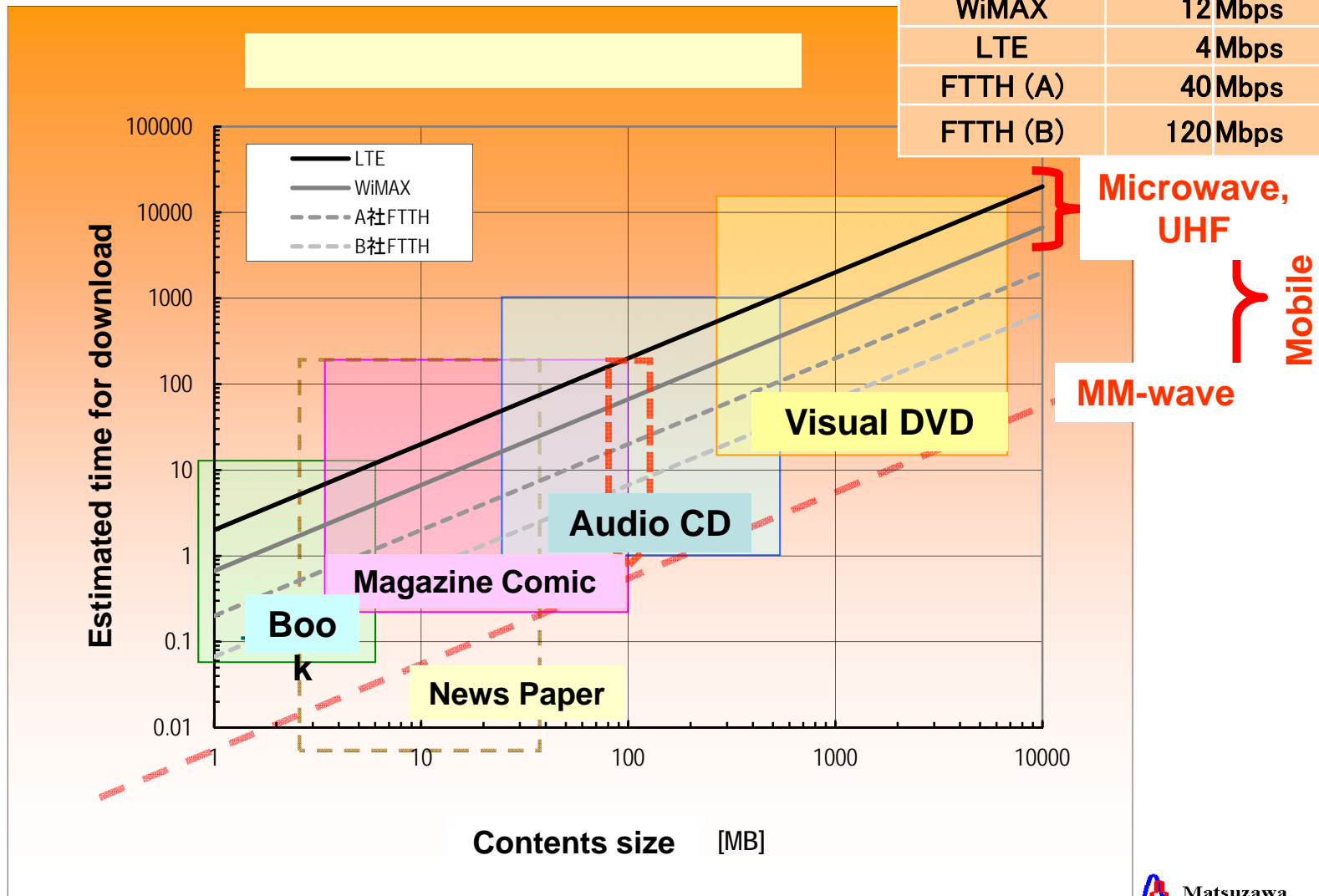


Time for big data contents download

60GHz MM wave can transfer the DVD data within several seconds

Measured average effective data rate as of Jan. 2011

WiMAX	12Mbps
LTE	4Mbps
FTTH (A)	40Mbps
FTTH (B)	120Mbps



WiGig Usage Models

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Instant Wireless Sync

- IP-based P2P applications
- Using I/O PAL



Kiosk Sync & Data Exchange



Wireless Display

- HD streams over HDMI or DP using A/V PAL
- CE, PE and HH usages



Cordless Computing

- Combination of Wireless display using A/V PAL, sync and I/O using I/O PAL



Distributed Peripherals



Internet Access

- Using native Wi-Fi, 802.11ad support



WiGig White Paper, "Defining the Future of Multi-Gigabit Wireless Communications" July 2010

Development of High Data Rate 60 GHz CMOS Transceivers

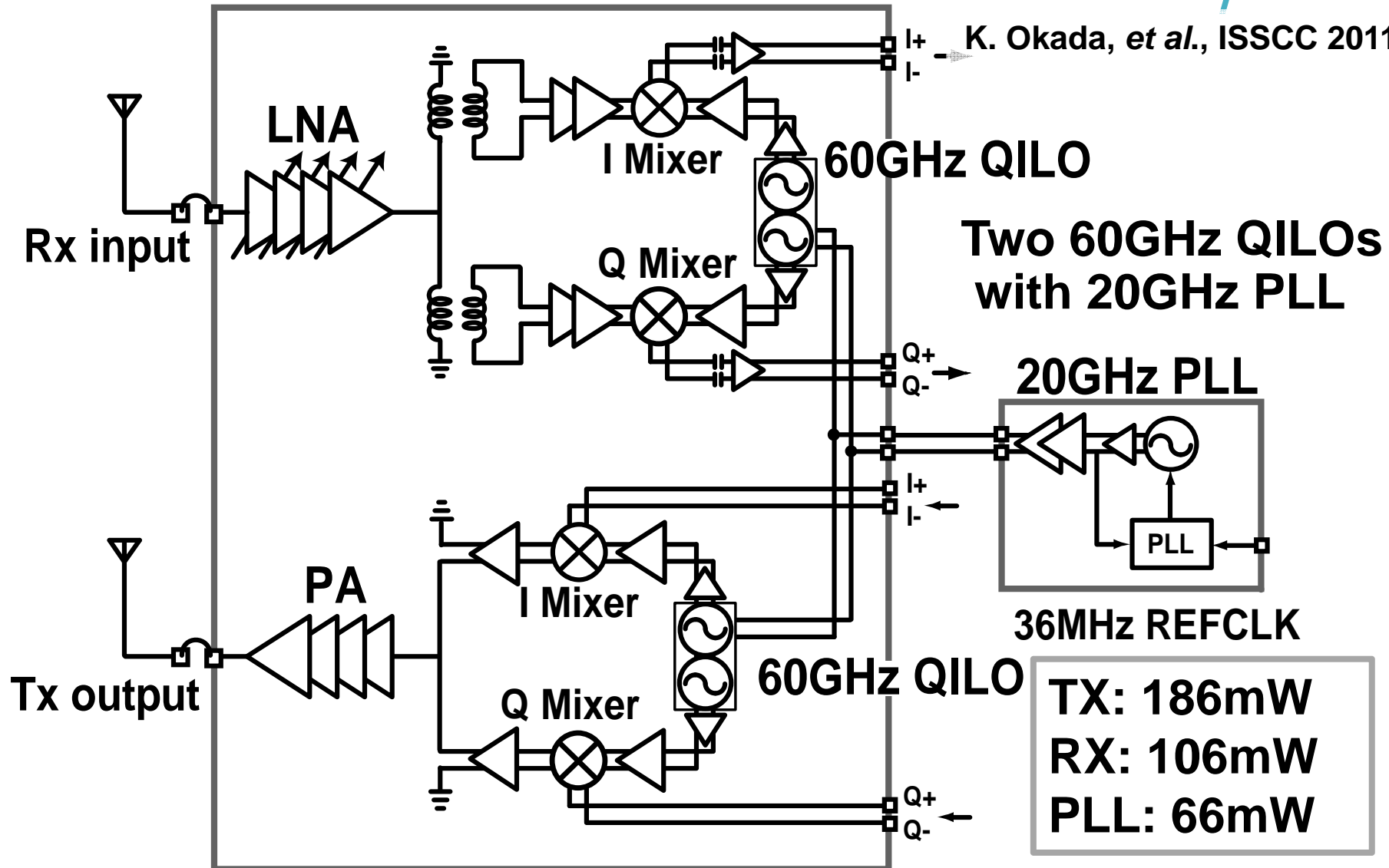
The 1st 60GHz transceiver on ISSCC 2011

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Direct conversion

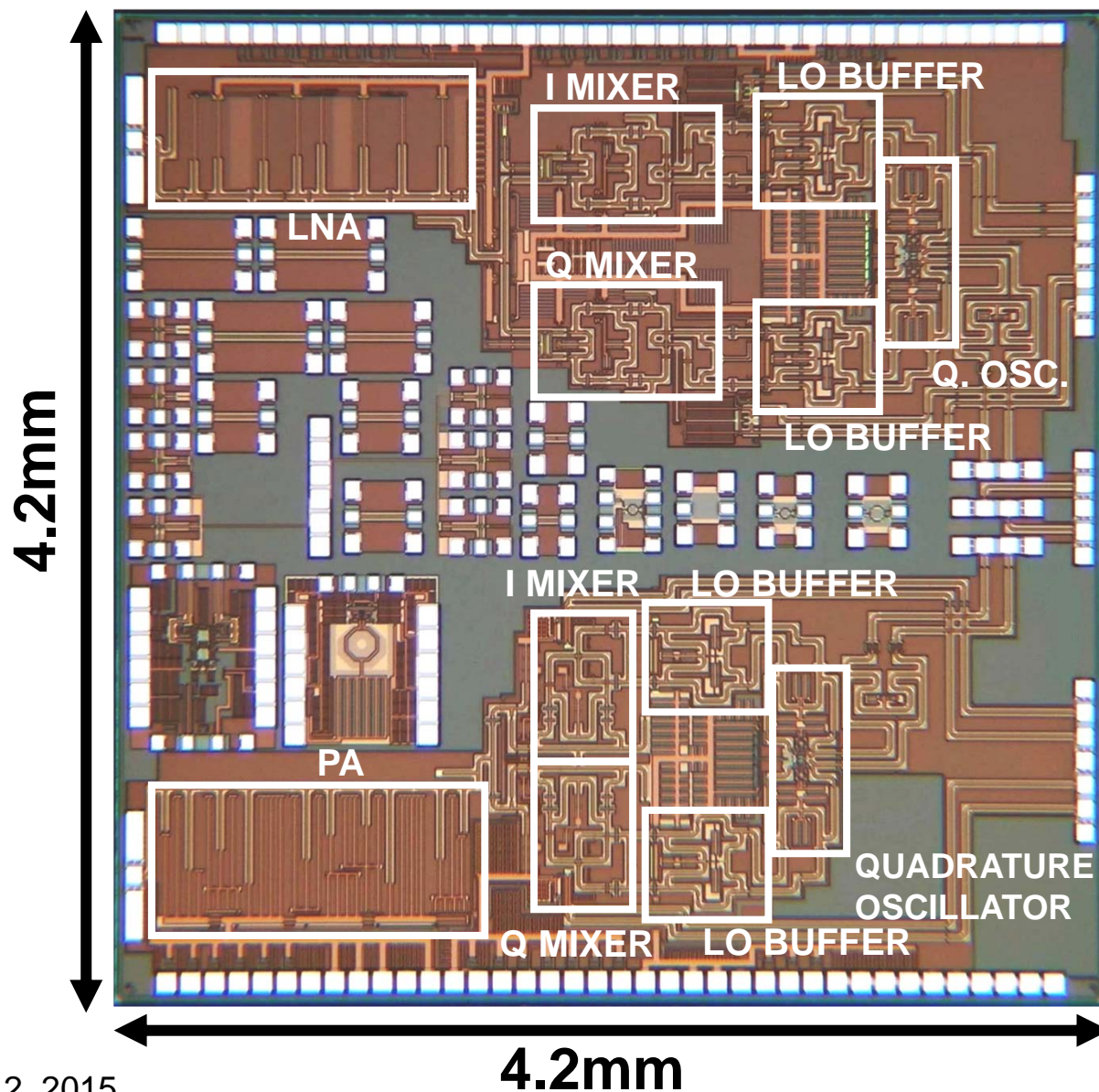
K. Okada, et al., ISSCC 2011



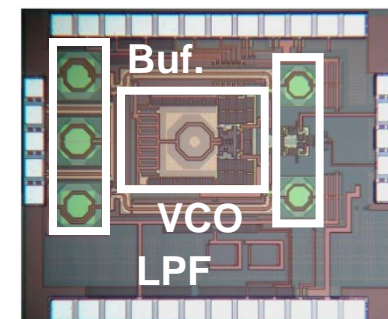
The 1st 60GHz transceiver on ISSCC 2011

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11Gb/s (16QAM)
8Gb/s (QPSK)



20GHz PLL
65nm CMOS
Rx:3.8mm²
Tx:3.5mm²
PLL:1.2mm²

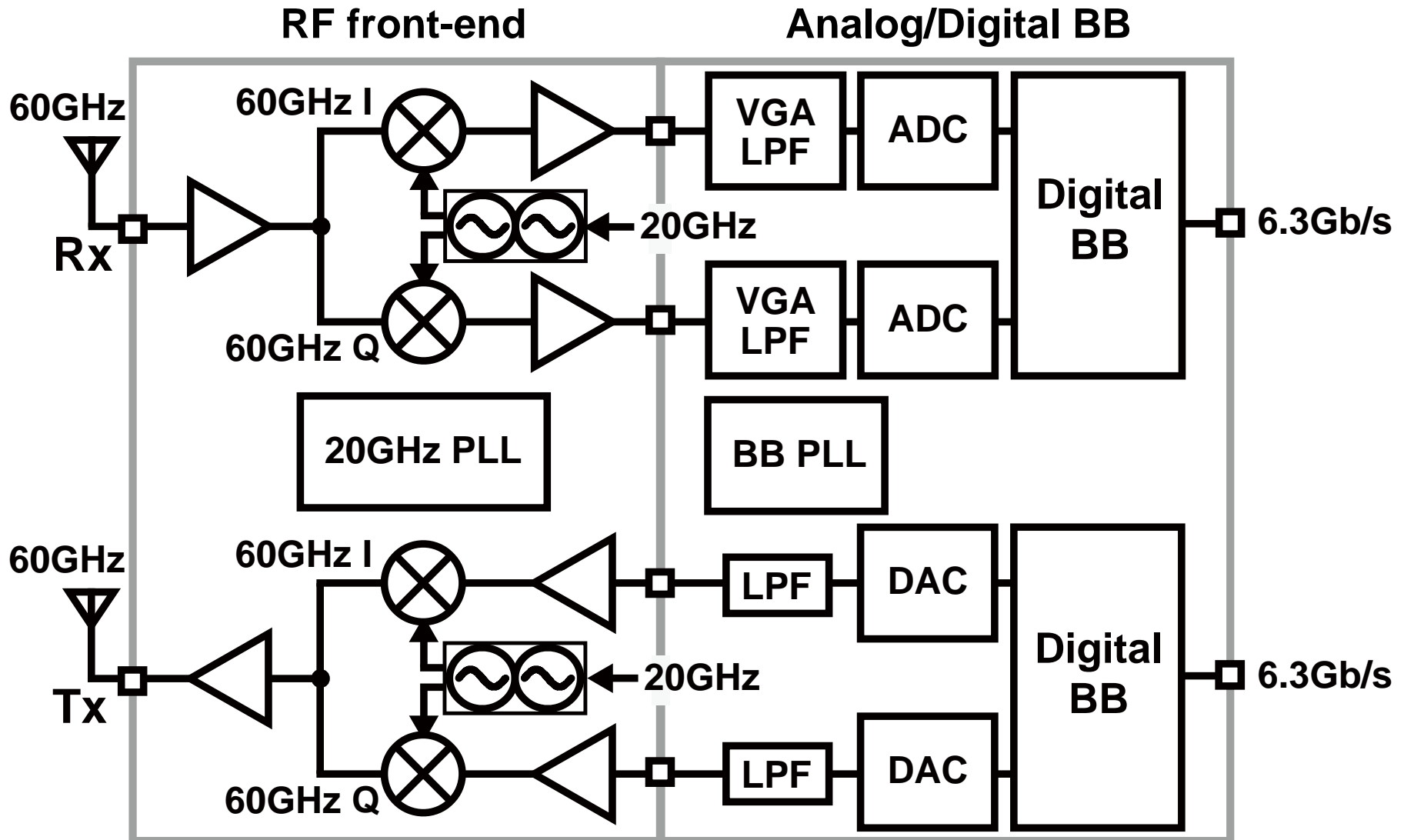
Nov.12. 2015.

The 2nd 60GHz Transceiver on ISSCC 2012

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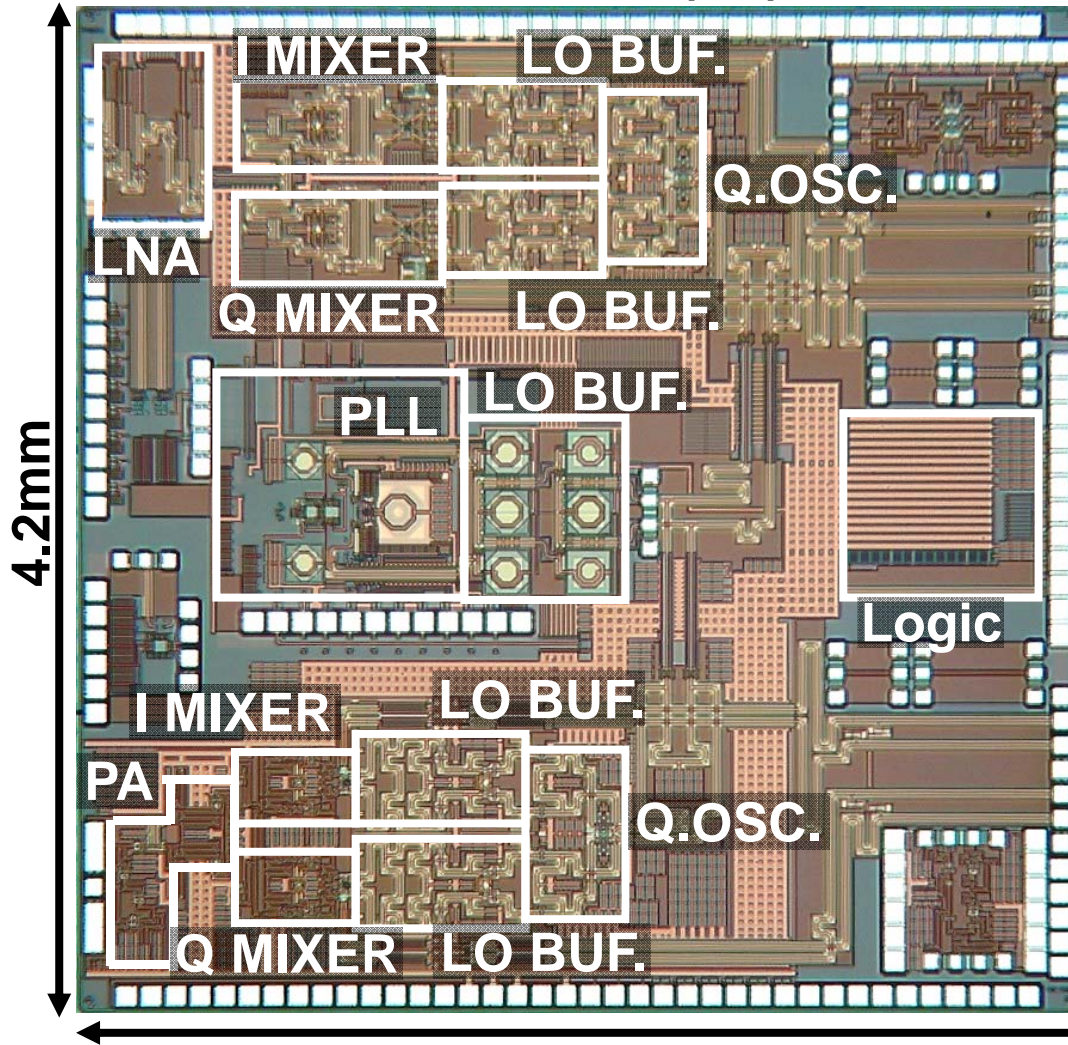
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RF and baseband chips have been developed



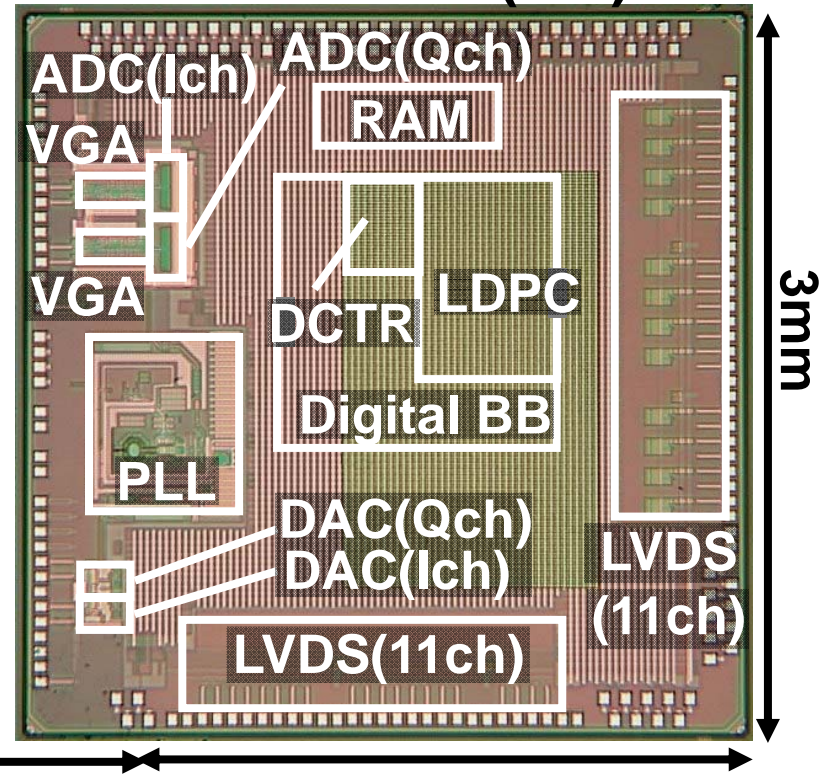
The 2nd 60GHz Transceiver on ISSCC 2012

Full transceiver has been developed.
65nm CMOS (RF)



10Gb/s (16QAM)
TX: 319mW
RX: 223mW

K. Okada, et al., ISSCC 2012
40nm CMOS (BB)



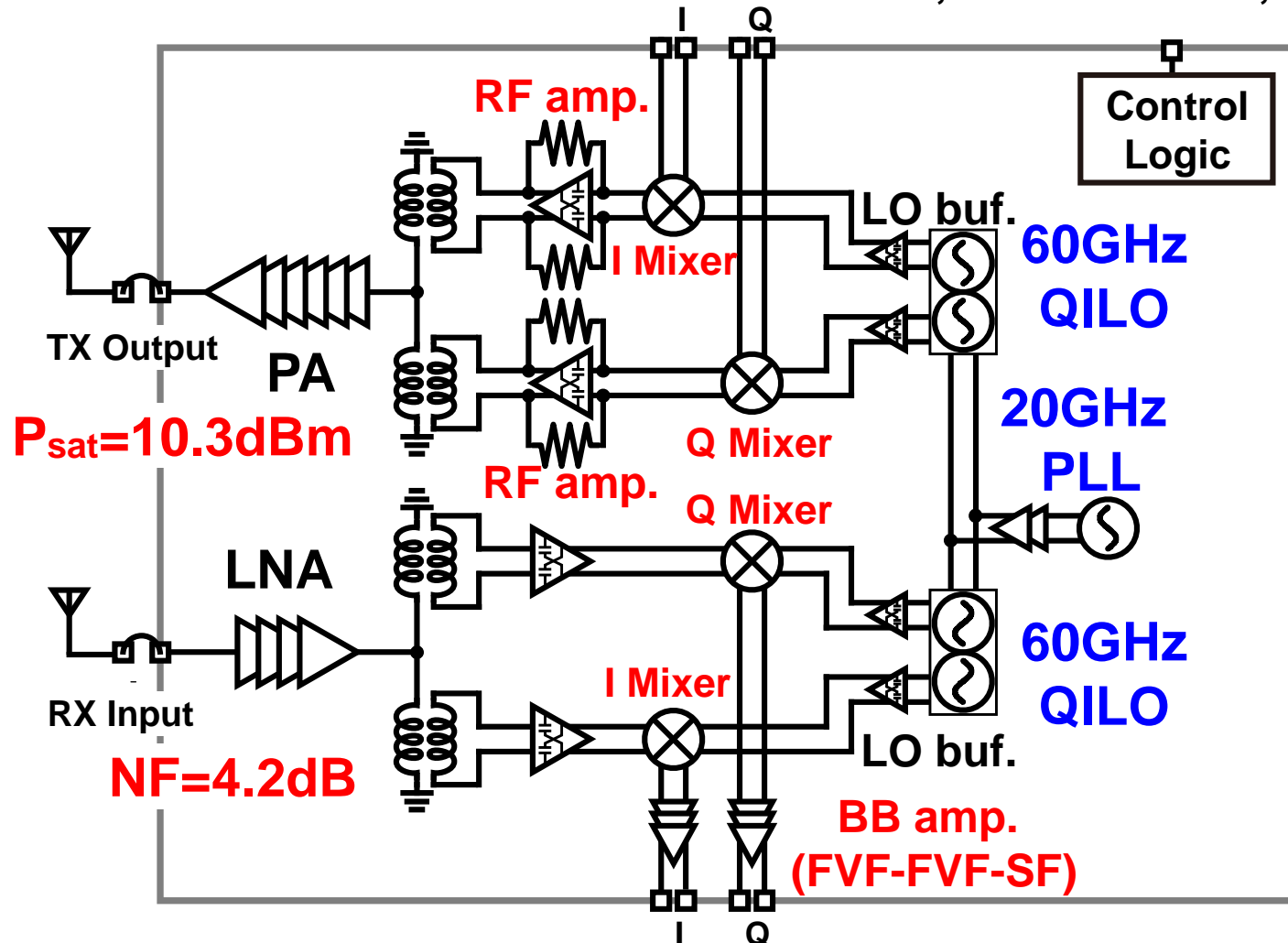
The 3rd 60 GHz Transceiver on ISSCC 2014

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Direct conversion method is used for wider bandwidth and low power

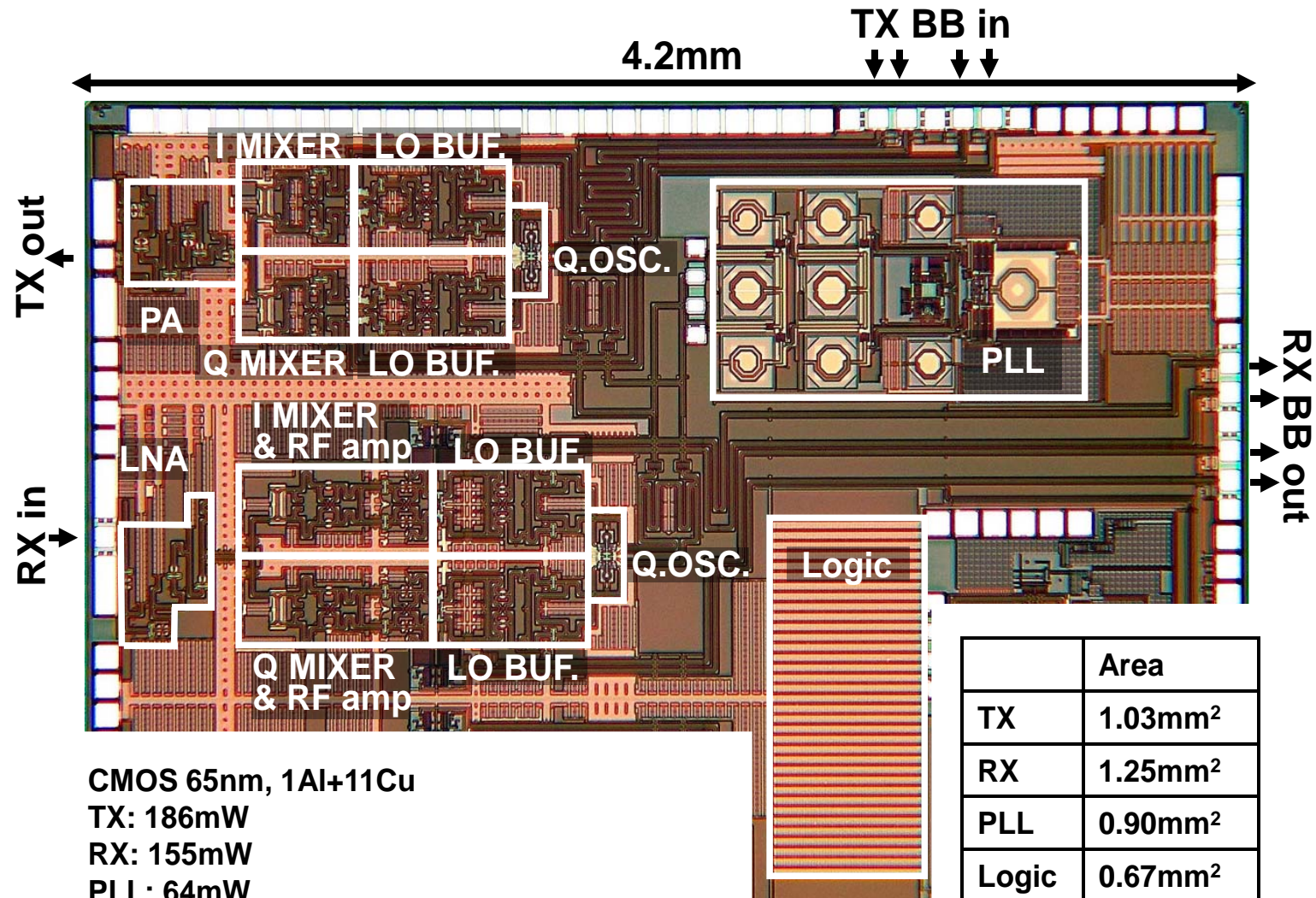
*K. Okada, A. Matsuzawa., ISSCC 2014



The 3rd 60 GHz Transceiver on ISSCC 2014

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Chip was fabricated in 65 nm CMOS technology

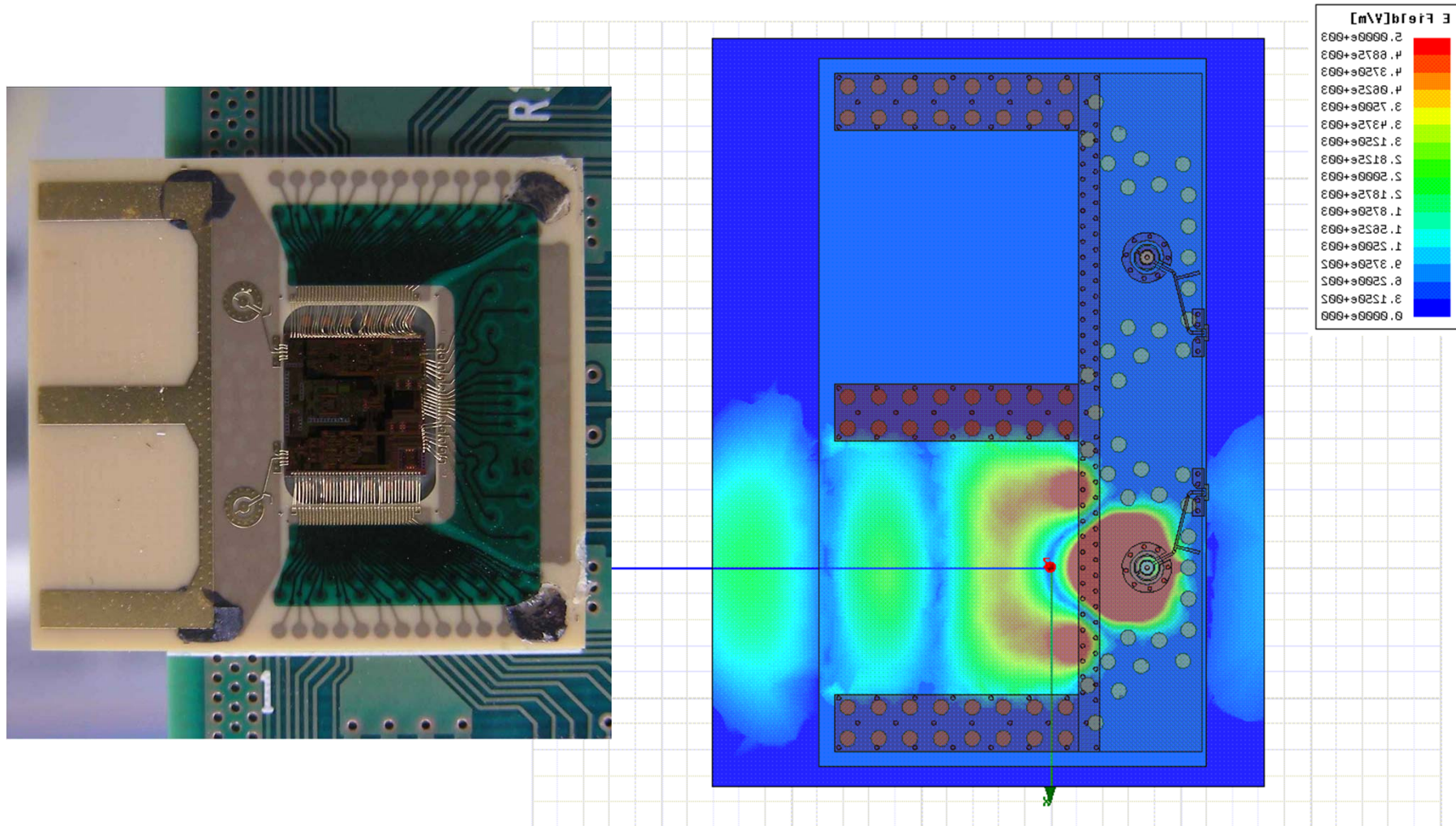


Chip with antenna in package

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The 60GHz RF chip are mounted on the antenna in package

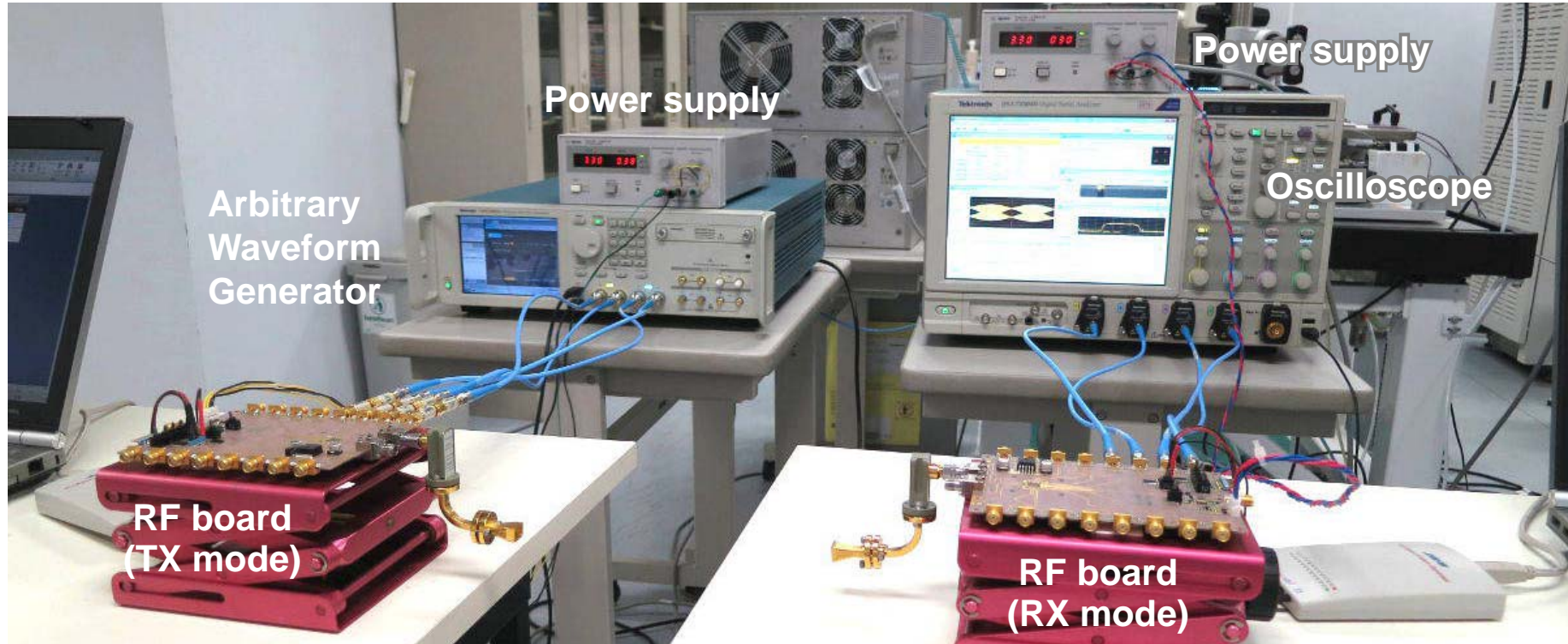


Chip measurement setup

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Chip was measured with high speed measurement system



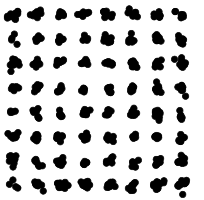
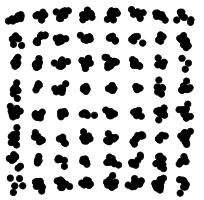
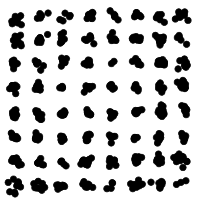
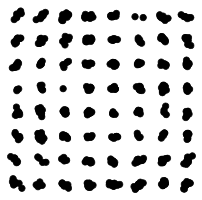
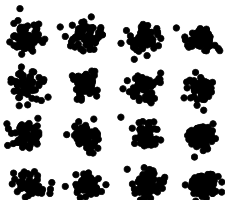
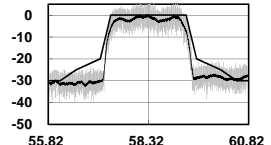
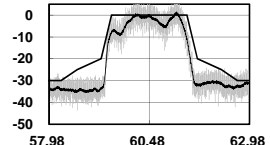
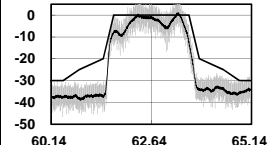
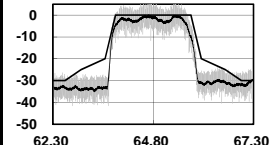
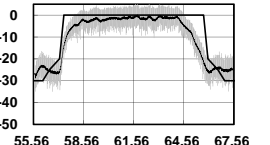
- 25-GS/s AWG
- 100-GS/s oscilloscope (33GHz BW)
- 14-dBi horn antennas

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Measured result

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The world's first 64 QAM has been realized
The world's fastest 28 Gbps has been attained.

Channel	ch.1 58.32GHz	ch.2 60.48GHz	ch.3 62.64GHz	ch.4 64.80GHz	ch.1-ch.4 bond
Modulation	64QAM				16QAM
Data rate	10.56Gb/s	10.56Gb/s	10.56Gb/s	10.56Gb/s	28.16Gb/s
Constellation					
Spectrum					
TX EVM	-27.1dB	-27.5dB	-28.0dB	-28.8dB	-20.0dB
TX-to-RX EVM	-24.6dB	-23.9dB	-24.4dB	-26.3dB	-17.2dB

Performance comparison

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Highest data rate with low EVM and power dissipation

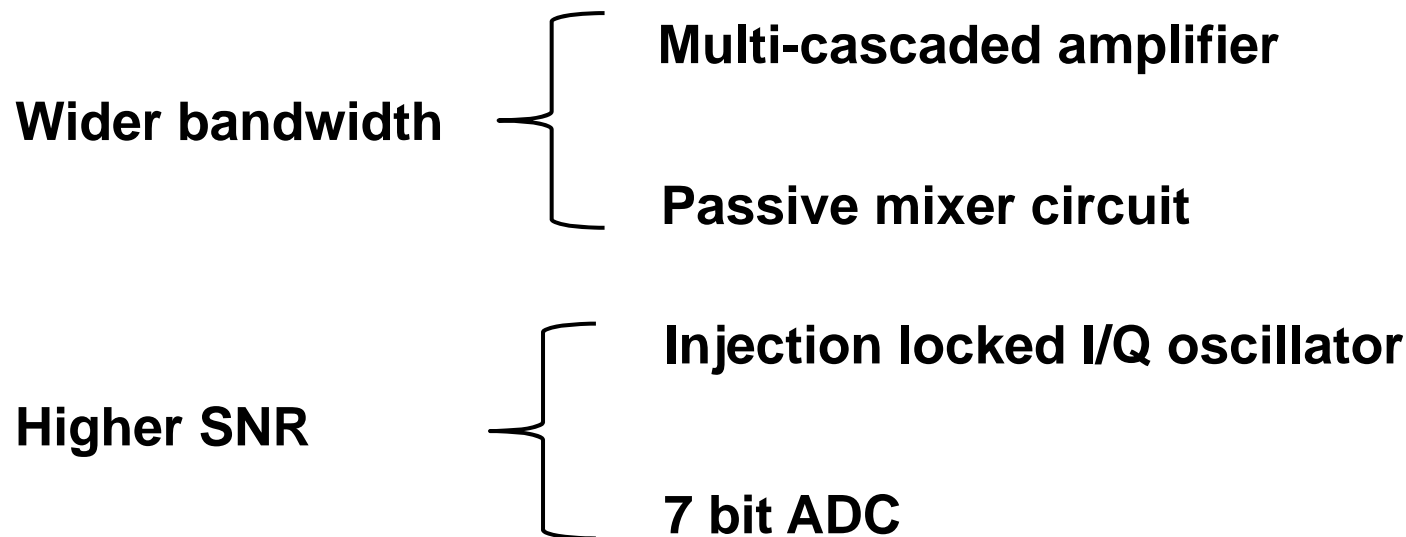
	Data rate / Modulation	TX-to-RX EVM	Integration	Power consumption
SiBeam [3]	7.14Gb/s(16QAM)	-19dB	65nm, 32x32-array heterodyne, TX, RX, LO	TX: 1,820mW RX: 1,250mW
Tokyo Tech [4, 5]	16Gb/s(16QAM) 20Gb/s(16QAM)[5]	-21dB	65nm, direct-conversion, TX, RX, LO, antenna, analog & digital BB	TX: 319mW RX: 223mW
IMEC [6]	7Gb/s(16QAM)	-18dB	40nm, direct-conversion, TX, RX, w/o PLL	TX: 167mW RX: 112mW
Toshiba [7]	2.62Gb/s(QPSK)	N/A	65nm, heterodyne, TX, RX, LO, antenna, analog & digital BB	TX: 160mW RX: 233mW
IMEC [8]	7Gb/s(16QAM)	-15dB	40nm, 4-array direct-conversion, TX, RX, LO, antenna	TX: 330mW RX: 284mW for 1 stream
Panasonic [9]	2.5Gb/s(QPSK)	-22dB	90nm, direct-conversion, TX, RX, LO, antenna, analog & digital BB	TX: 347mW RX: 274mW
Broadcom [10]	4.6Gb/s(16QAM)	-20dB	40nm, 16-array heterodyne, TX, RX, LO, antenna, analog/digital BB	TX: 960mW RX: 1190mW
This work	10.56Gb/s(64QAM) 28.16Gb/s(16QAM)	-26dB	65nm, direct-conversion, TX, RX, LO	TX: 251mW RX: 220mW

High Data Rate Circuits Design

Wider bandwidth and higher SNR are required to attain higher data rate

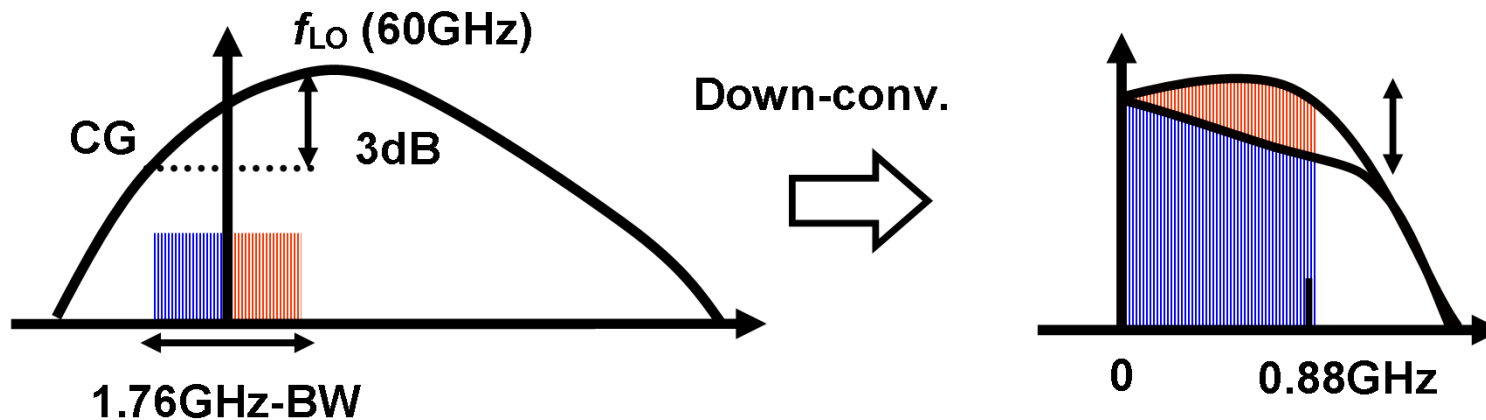
Shannon's theory

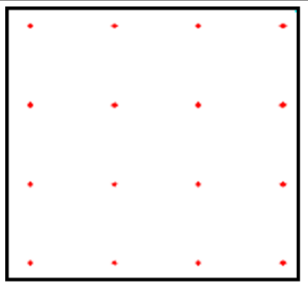
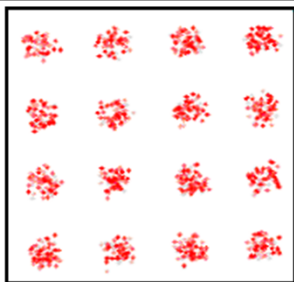
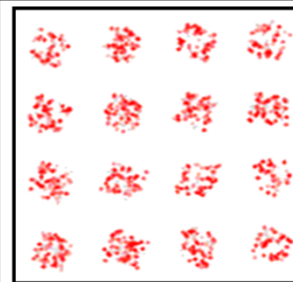
$$D_{rate} = BW \log_2 \left(1 + \frac{S}{N} \right)$$



Effect of the gain flatness

Poor gain flatness makes ISI (Inter Symbol Interference) due to different gain for plus frequency and minus frequency.

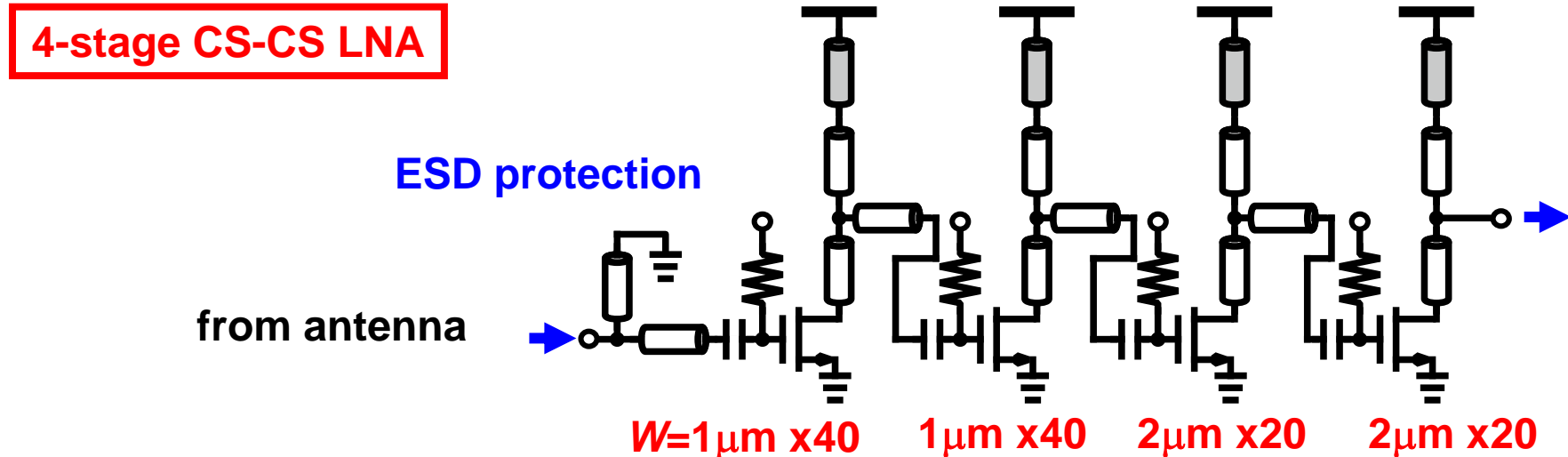
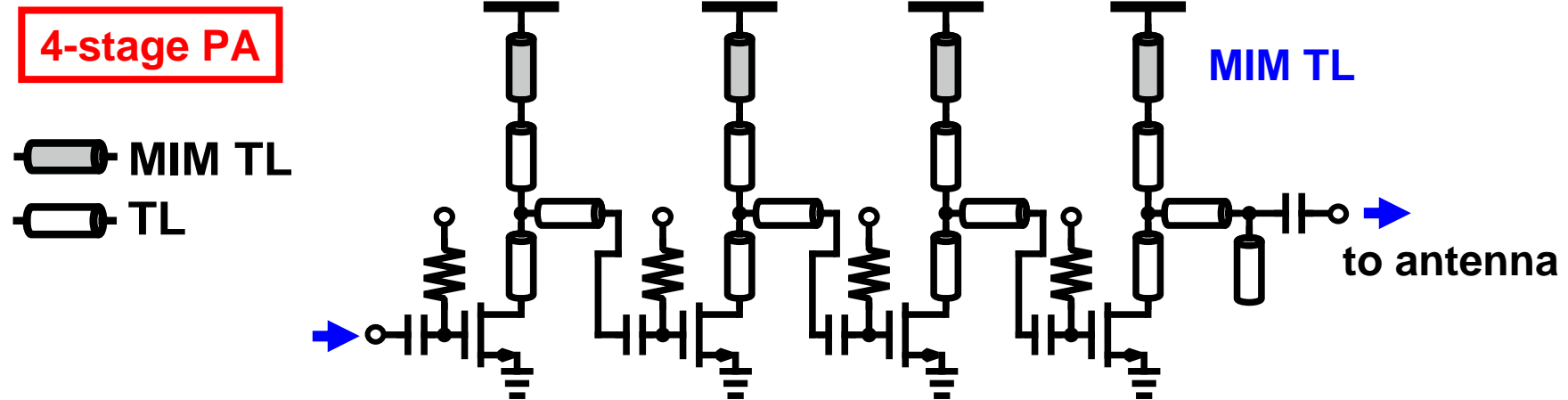


Gain Flatness	0dB	2dB	3dB
BER	~0	1.3e-5	3e-3
Constellation			

Multi-cascaded RF amplifiers

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Multi-cascaded RF amplifier can increase the gain flatness due to the distributed resonant frequencies.

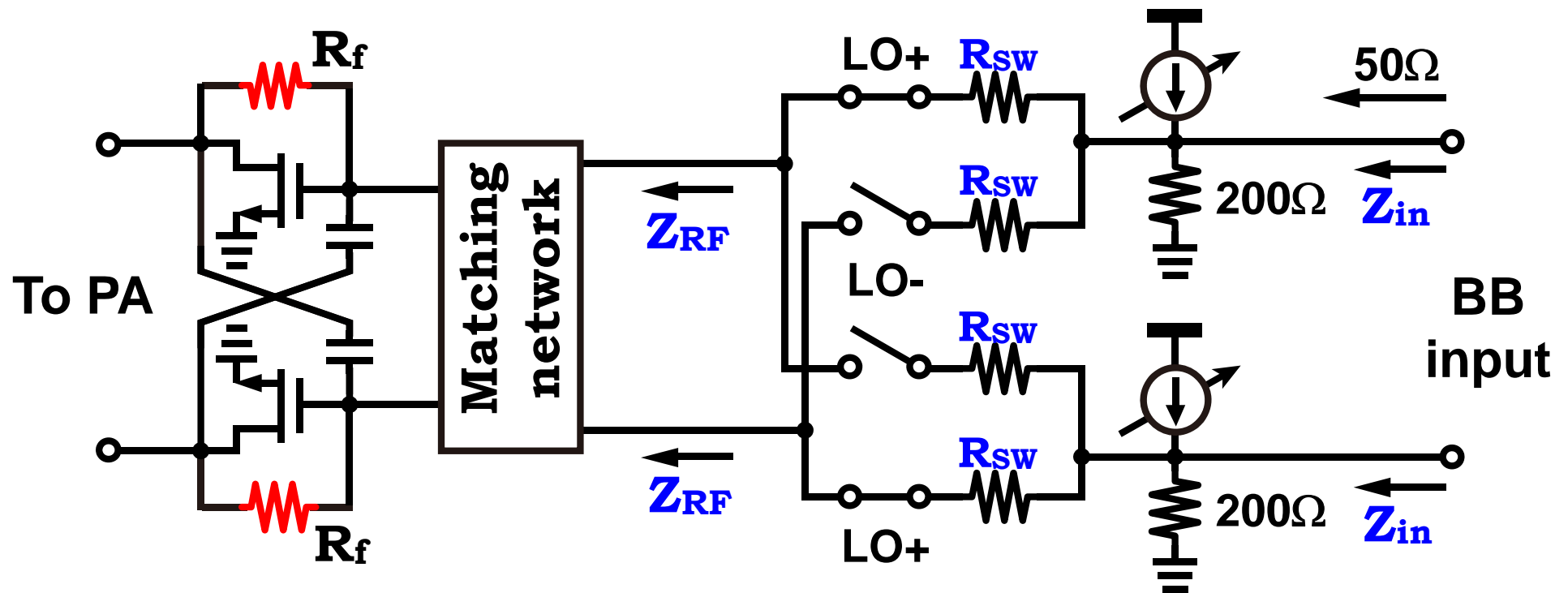


Mixer circuit in TX

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Passive mixer with resistive feedback RF amplifier can realize
Widely flat impedance, rather than LC impedance matching method.

$$Z_{in}(\omega) \approx 200\Omega // \left\{ R_{SW} + \frac{8}{\pi^2} \text{Re}[Z_{RF}(\omega_{LO})] \right\}$$

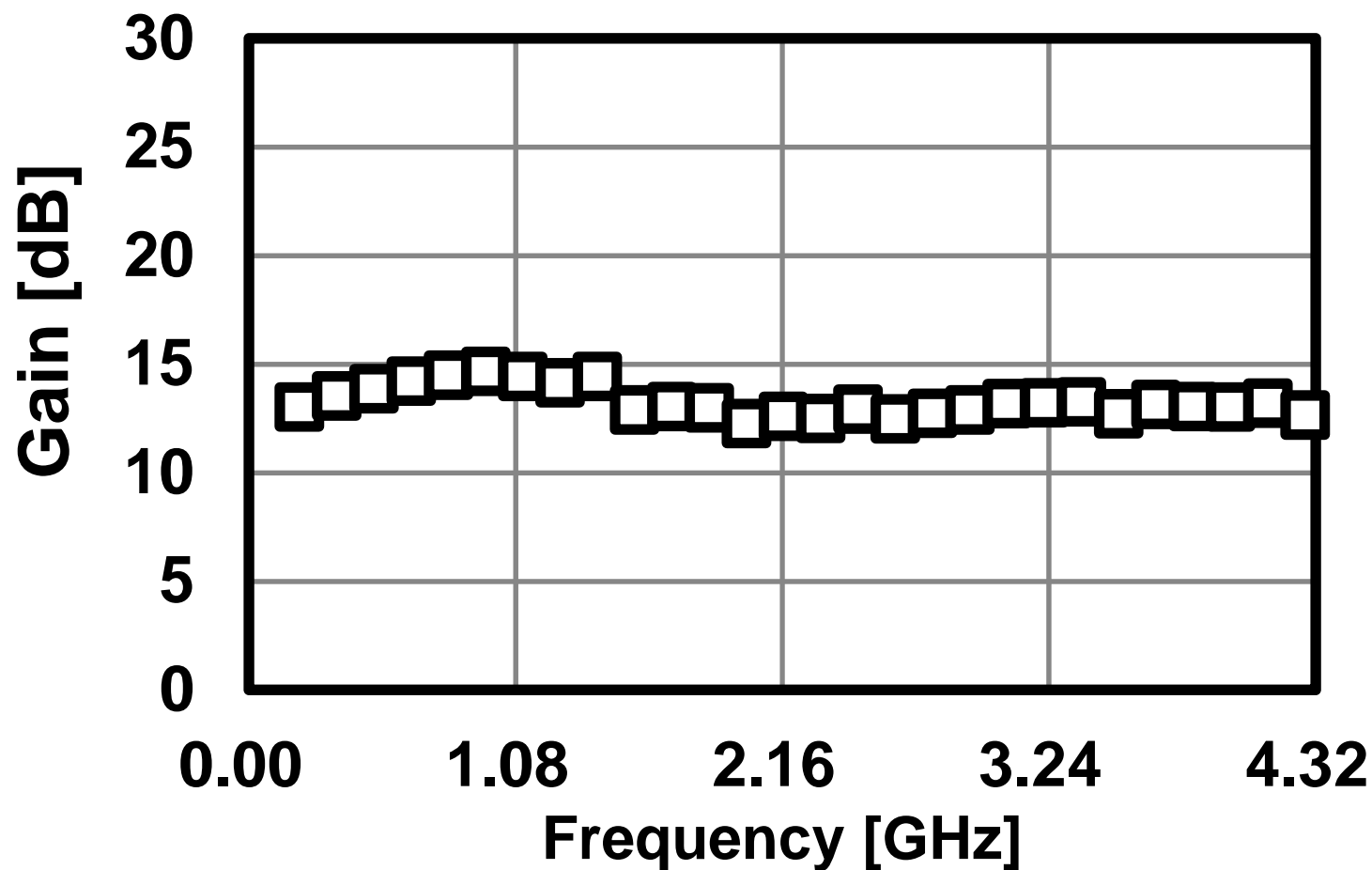


Measured gain of TX circuit

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The gain flatness of 2 dB is attained for the band width of 4 GHz.

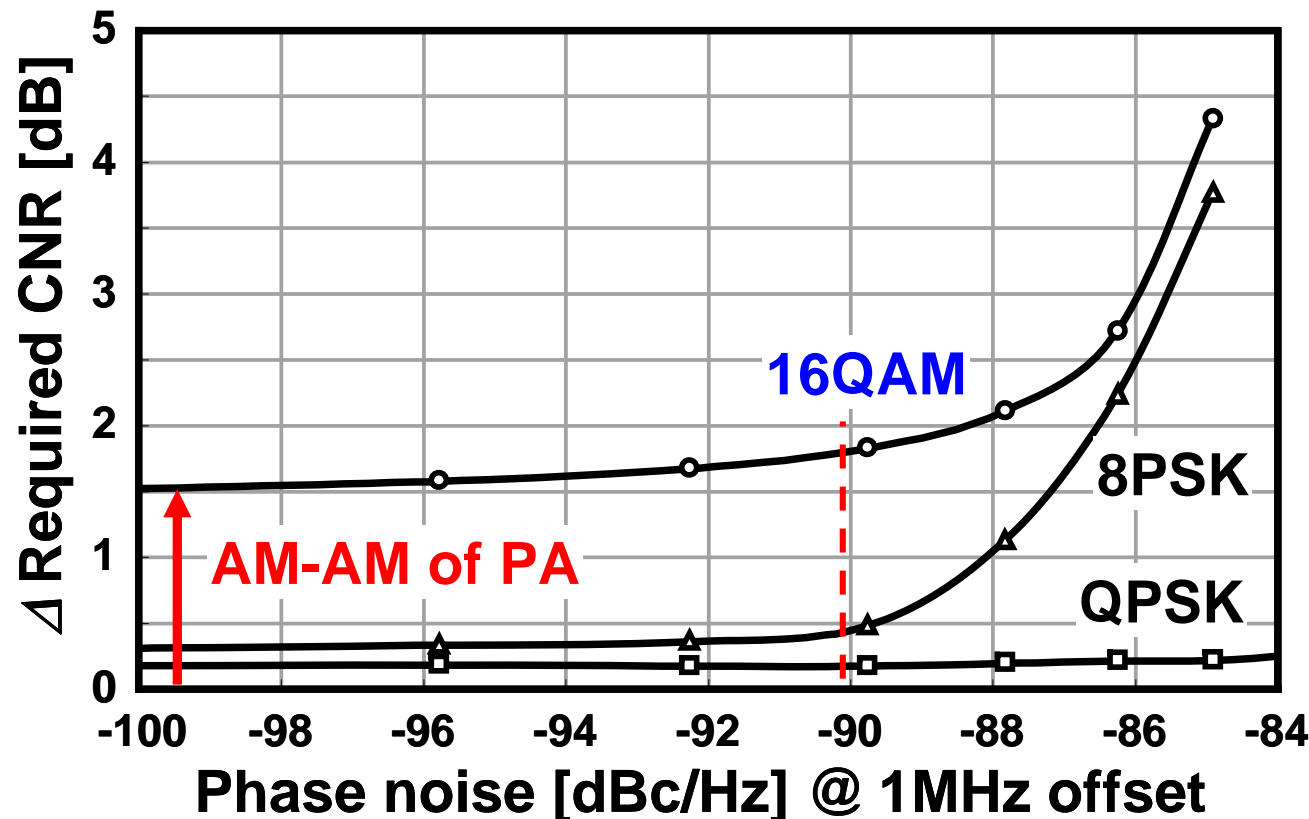


Required phase noise of IQ-VCO for 16QAM

A phase noise of LT. $-90\text{dBc/Hz}@1\text{MHz}$ is required for 16QAM systems

A reported phase noise of 60GHz IQ VCO is $-76\text{dBc/Hz}@1\text{MHz}$ at most

K. Scheir, et al., ISSCC, pp. 494-495, Feb. 2009.

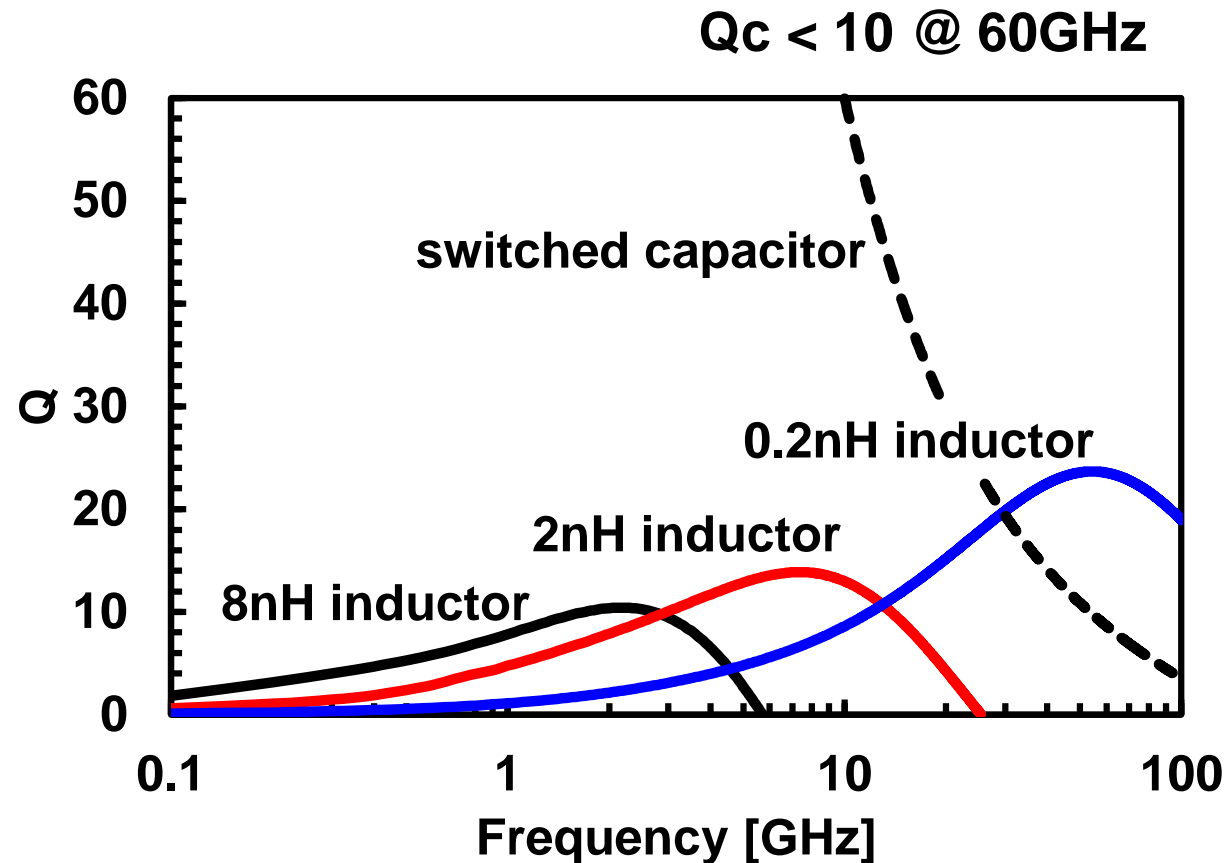


Q of inductors and capacitor / 25

Q of capacitor is rapidly degraded with frequency.

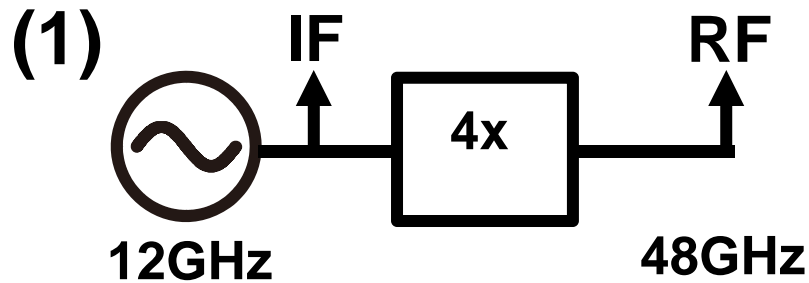
Q of Less than 10 at 60 GHz at most.

→ Low phase noise 60 GHz VCO is hard to be realized.



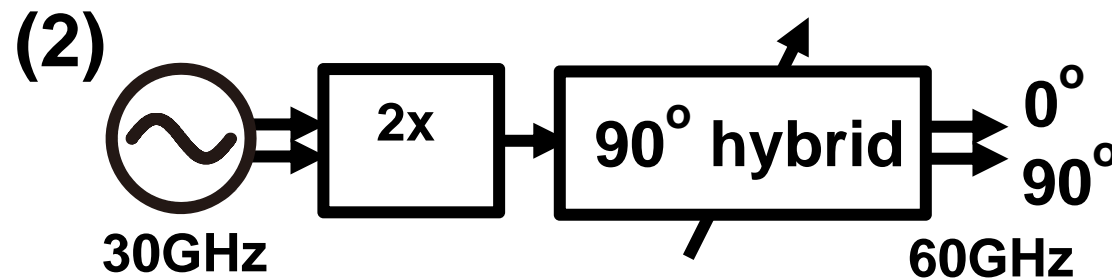
Frequency Multiplier

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- for hetero-dyne TRX
- reasonable for PN and FTR

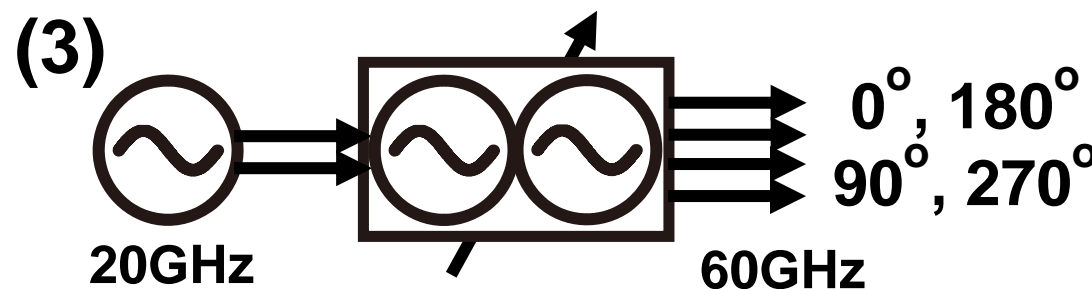
*S. Emami, *et al.*, ISSCC 2011



- 30GHz is too high for PN and FTR
- I/Q phase calibration is required.

(20GHz x 3, 15GHz x 4 are OK.)

**C. Marcu, *et al.*, ISSCC 2009



- 60GHz QILO***
- good for PN and FTR

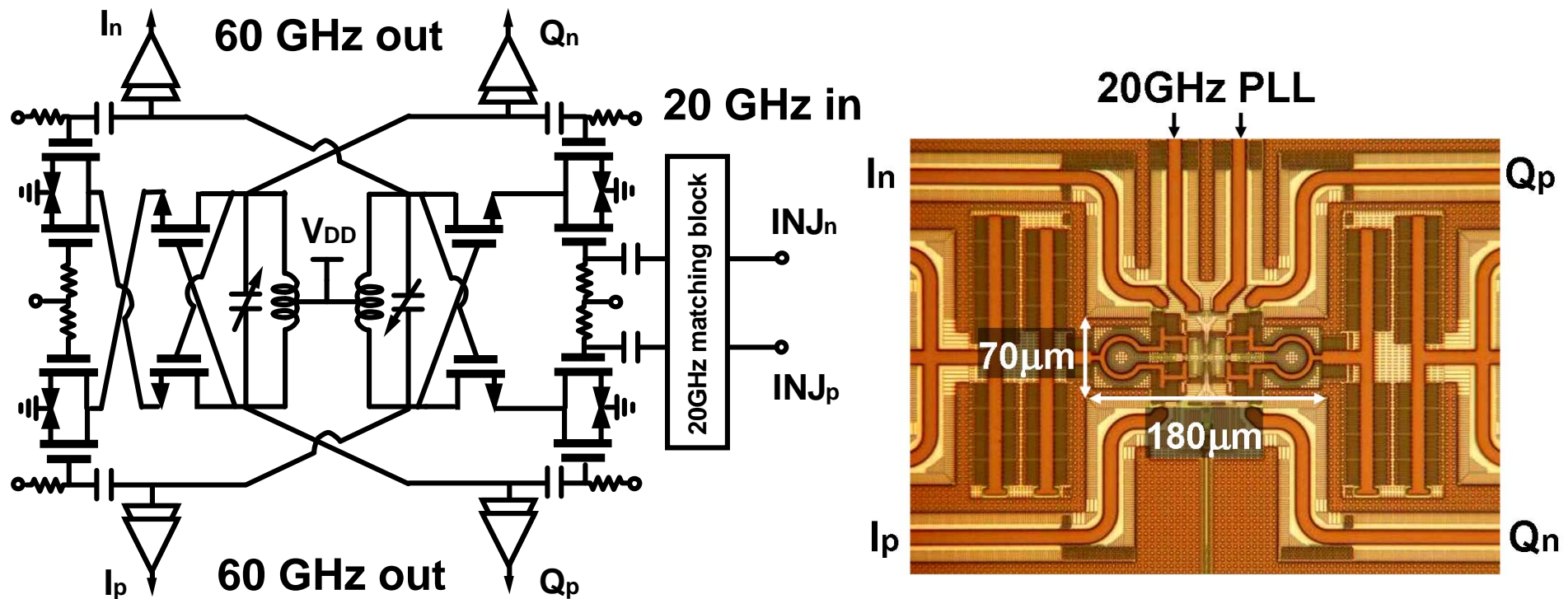
***W. Chan, *et al.*, ISSCC 2008

Injection locked 60GHz I/Q VCO

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We have developed the injection locked 60 GHz I/Q VCO
The 60 GHz quadrature VCO is injected by 20 GHz PLL



A. Musa, K. Okada, A. Matsuzawa., in A-SSCC
Dig. Tech. Papers, pp. 101–102, Nov. 2010.

60GHz Quadrature LO Design

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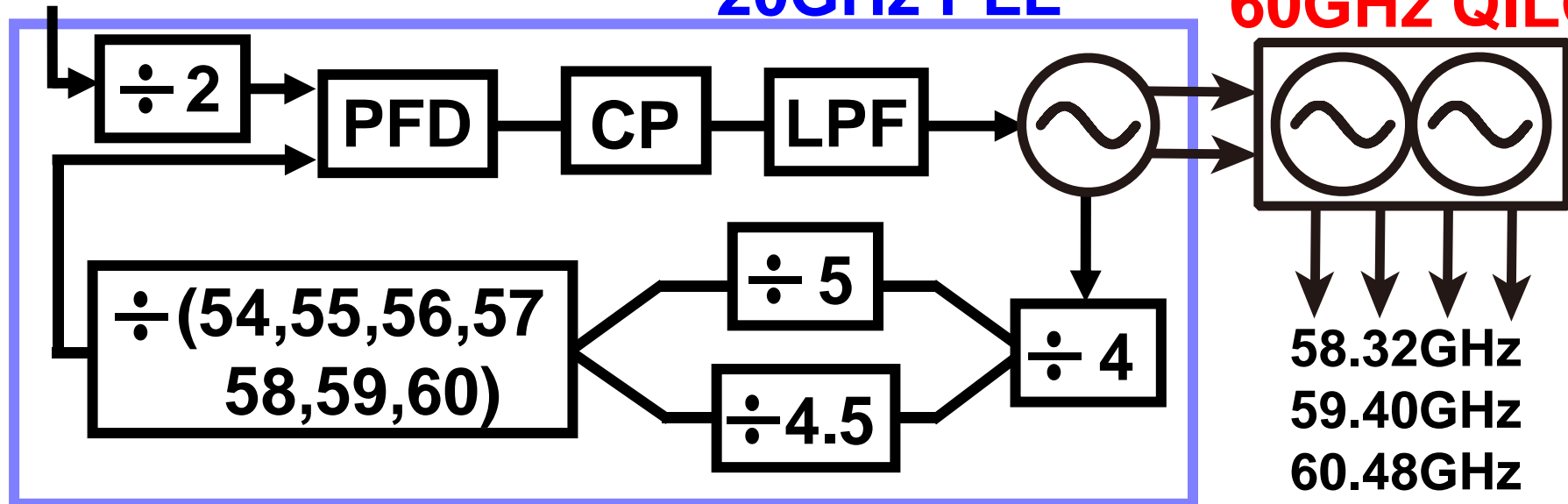
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*K. Okada, et al., ISSCC 2011

36/40MHz ref.

20GHz PLL

60GHz QILO*

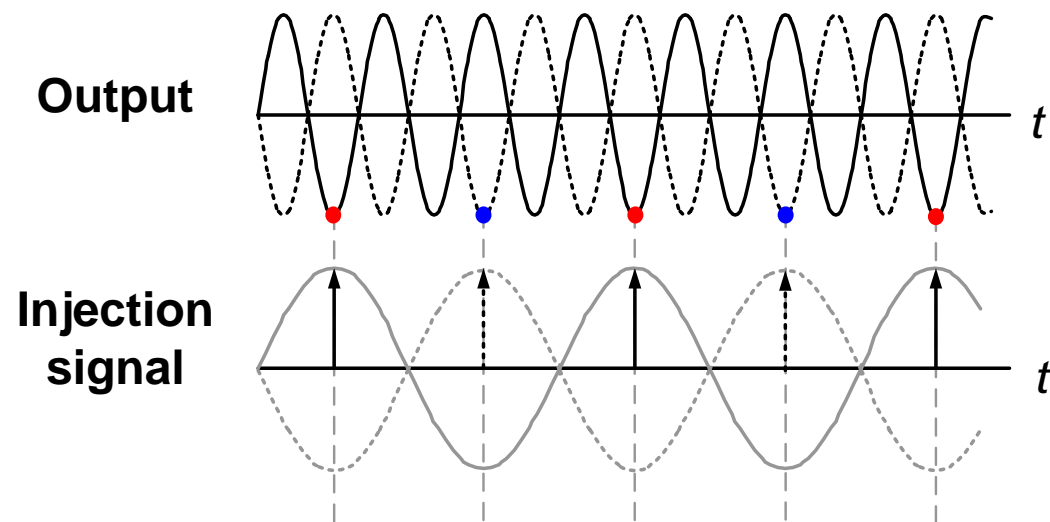
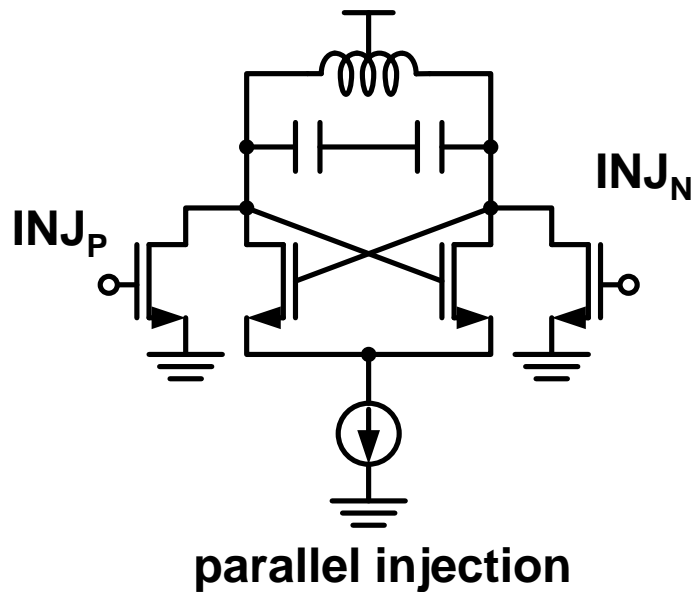


- 20GHz PLL: 64mW
- 60GHz QILO: 18mW(TX)&15mW(RX)
- QILO frequency range: 58-66GHz
- Phase noise improvement by **injection locking***
- **-96.5dBc/Hz** @ 1MHz at 61.56GHz

Injection locking technique

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Injection locking technique is a very important circuit technique for high frequency signal generation and frequency divider. Phase noise of the oscillator is mandated by the injection signal.



Phase noise

$$PN_{ILO} = PN_{INJ} + 20 \log(N)$$

N: Multiple number

9.5dB @ N=3

Locking frequency range

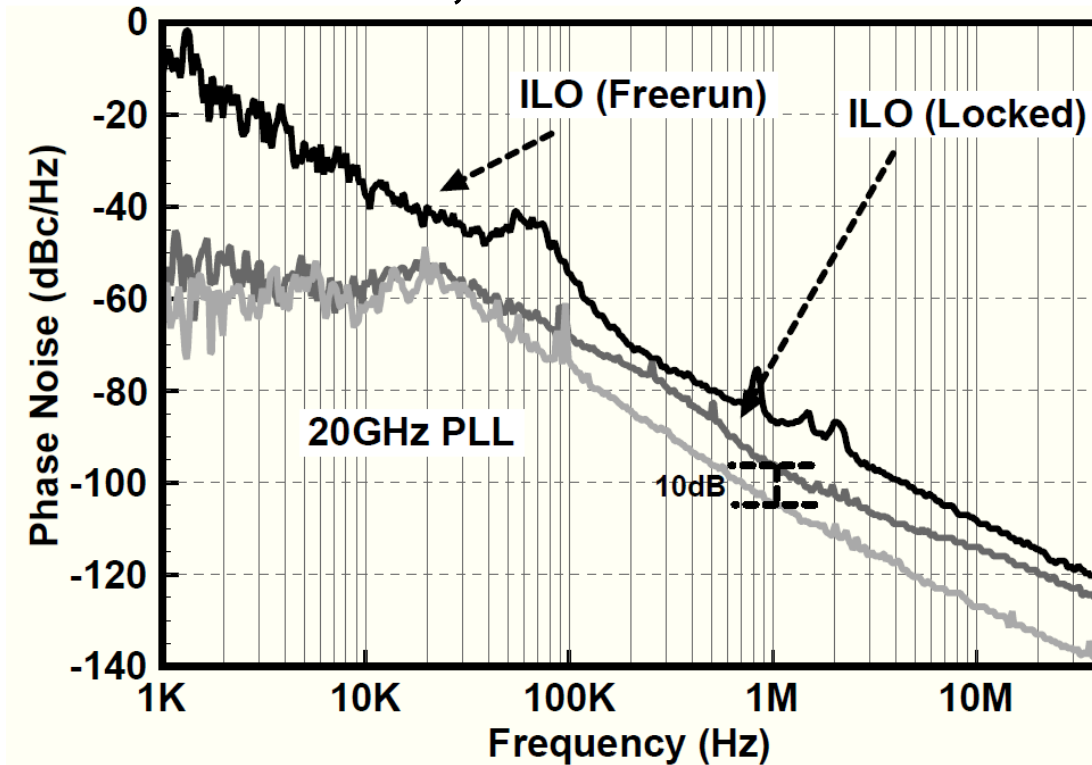
$$f_L \approx \frac{f_o}{2Q} \cdot \frac{I_{inj}}{I_{OSC}}$$

Low phase noise can be realized / 30

Quadrature injection locked 60GHz oscillator with 20GHz PLL
Low phase noise of -96dBc/Hz @1MHz. Previous one is -76dBc/Hz @1MHz

Best phase noise is achieved.

58-63GHz, -96dBc/Hz -1MHz offset



A. Musa, K. Okada, A. Matsuzawa., in A-SSCC
Dig. Tech. Papers, pp. 101–102, Nov. 2010.

Basic Design Method for 60GHz

CMOS RF Circuits

Gain and Noise; f_{\max} and f_T

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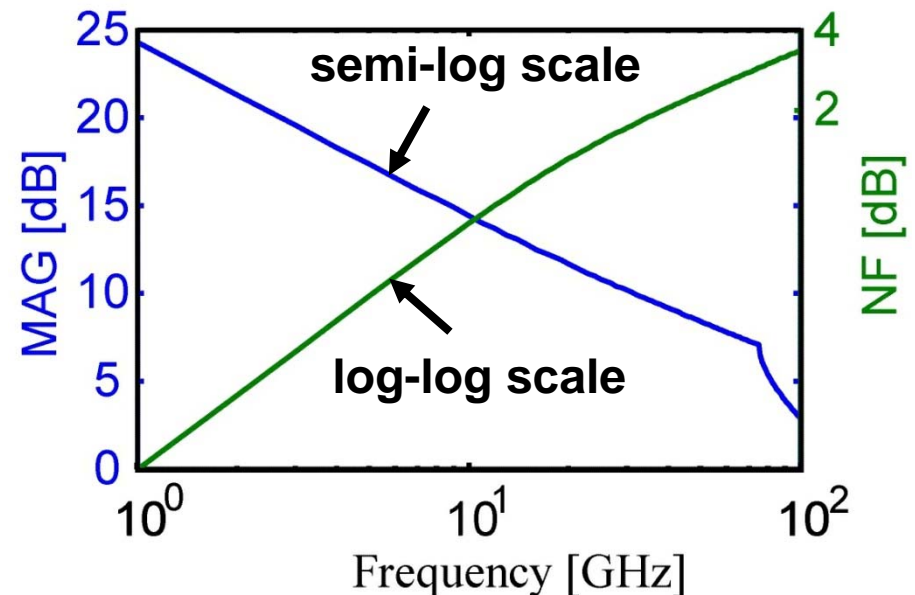
Gain and noise are mainly determined by f_{\max} and f_T of Transistor

☹ Lower gain

☹ MAG is inversely proportional to the logarithm of the operating frequency f_c .

☹ Higher noise

☹ NF_{\min} is proportional to the operating frequency f_c .



65nm NMOS

$W_f=2.5\mu\text{m}$, $N_f=32$, $V_{gs}=0.8\text{V}$ and $V_{ds}=0.8\text{V}$.

$$G_{\max} \approx \frac{f_{\max}}{f_c}$$

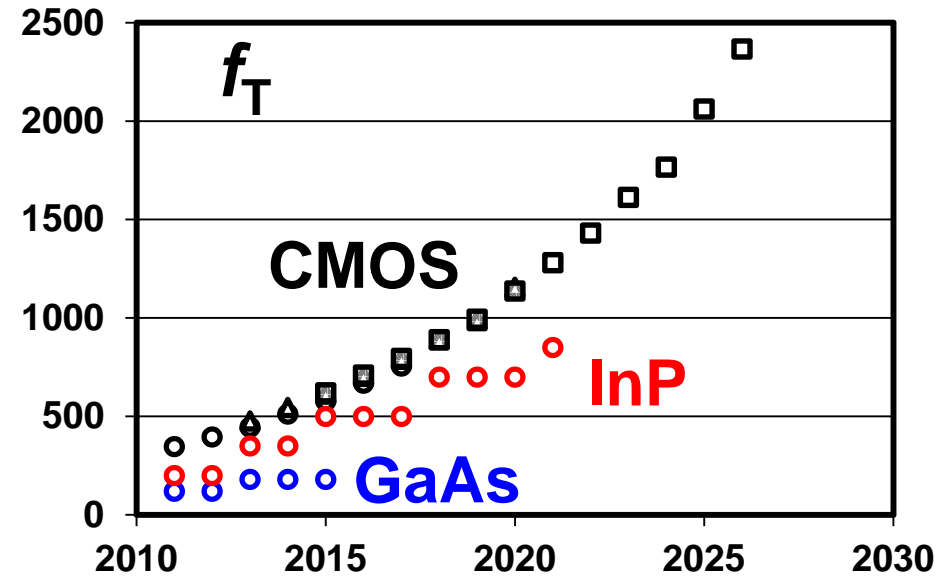
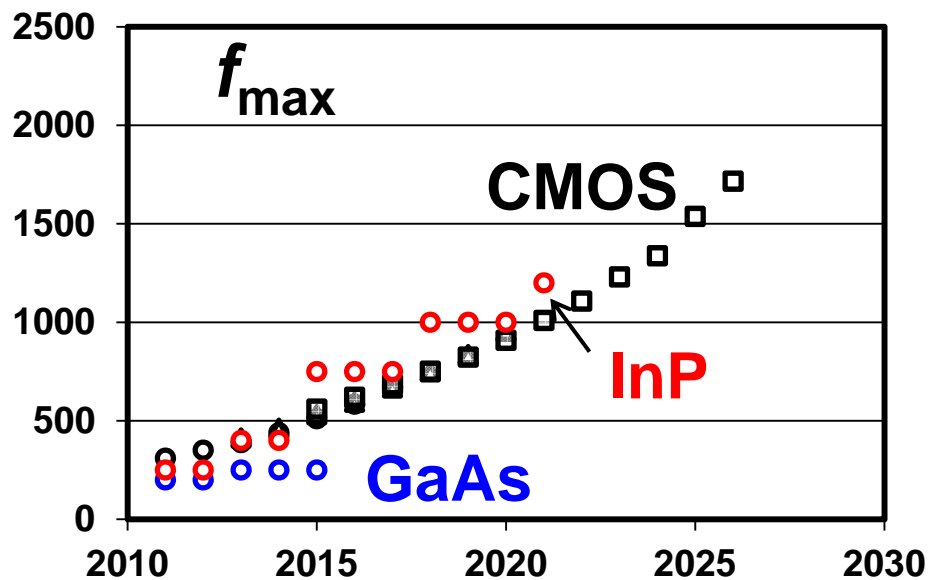
$$NF_{\min} \approx 1 + \left(\frac{f_c}{f_T} \right) \sqrt{1.3g_m(R_g + R_s)}$$

Basic RF performances

f_{\max} and f_T of MOS transistor will increase continuously.
Gain and NF will be improved by using future CMOS technology.

$$G_{\max} \approx \frac{f_{\max}}{f_c}$$

$$NF_{\min} \approx 1 + \left(\frac{f_c}{f_T} \right) \sqrt{1.3g_m(R_g + R_s)}$$



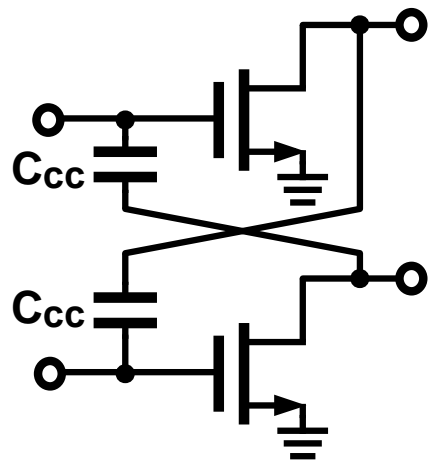
- Bulk CMOS
- △ Ultra-Thin-Body Fully-Depleted (UTB FD) SOI
- Multi-Gate MOSFETs

ITRS RFAMS 2011.

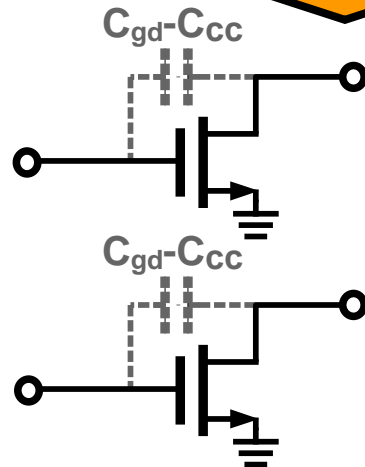
Cross coupled feedback capacitors / 34

Differential circuit

Cross coupled feedback capacitors in a differential circuit can reduce the effective capacitance to increase the gain of 6dB at 60GHz.

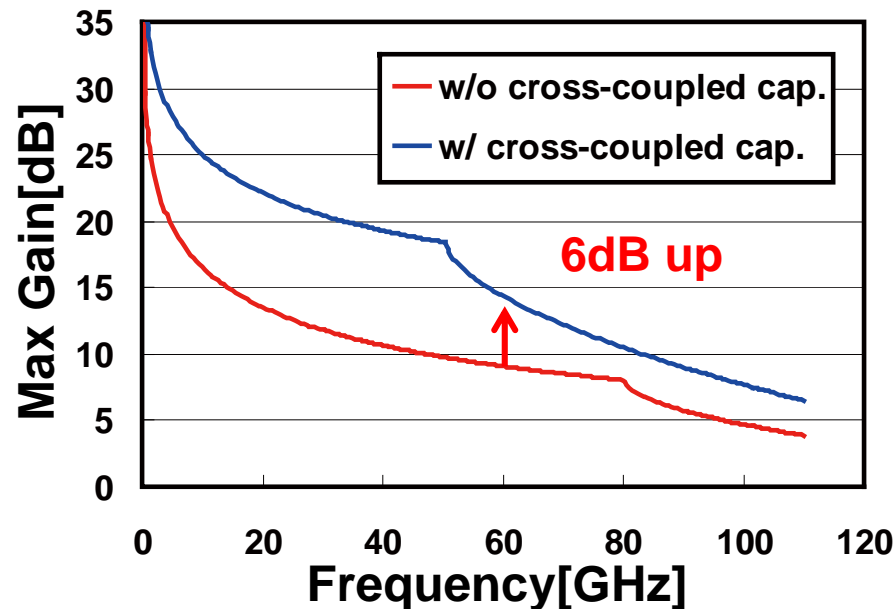


Capacitance is cancelled



$$f_{\max} = \frac{f_T}{2\sqrt{R_g g_m C_{gd} / (C_{gs} + C_{gd}) + (R_g + r_{ch} + R_s) g_{ds}}}$$

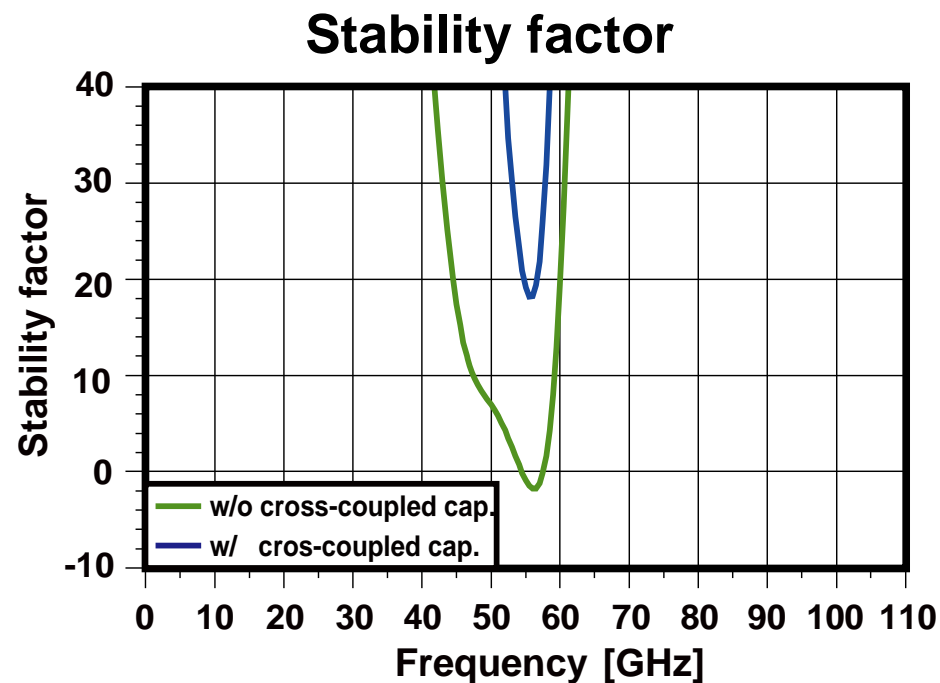
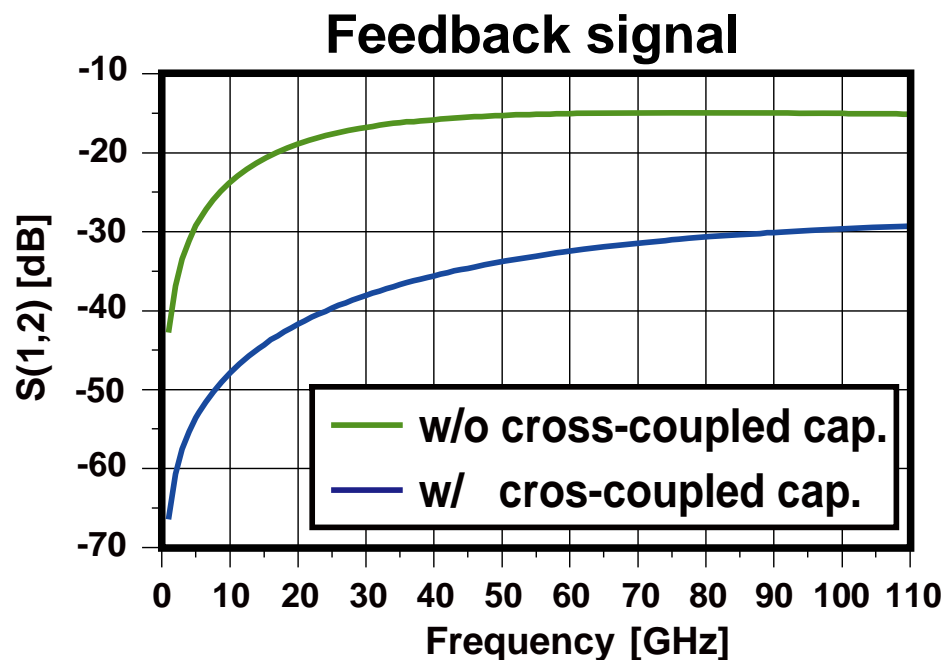
This term is reduced



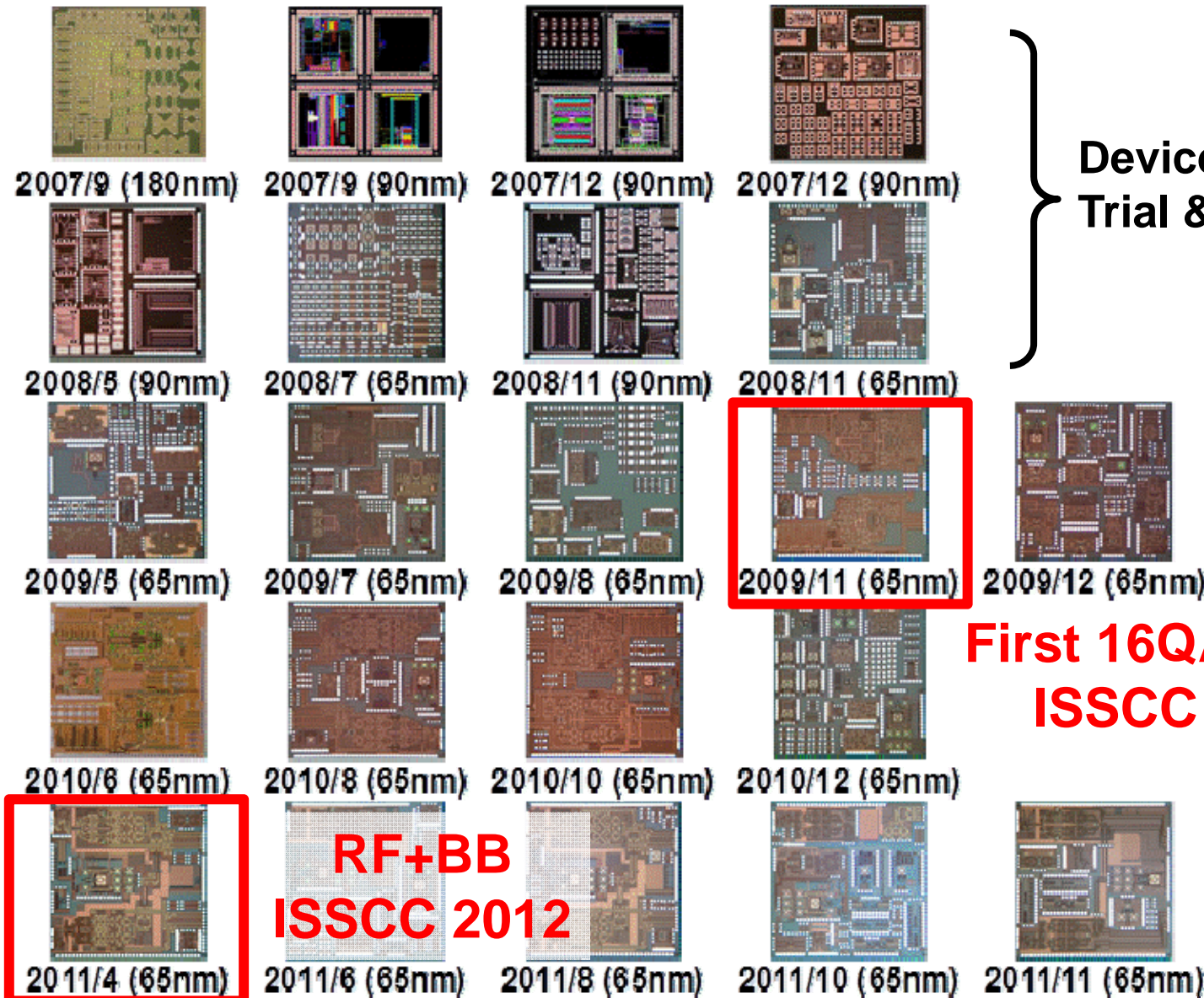
Y. Natsukari, et al., VLSI Circuits, Dig. Tech. Papers, pp. 252–253, June 2009.

W. L. Chan, et al., ISSCC. Tech. Dig., pp. 380–381, Feb. 2009.

Feedback signal is suppressed by the cross coupled capacitors and this increase the stability of amplifier.



Development history of 60GHz circuits



In-house PDK

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See inside of top_pdk and top_meas.
top_pdk top_meas

To see simulation results, copy top_pdk.dds and top_meas.dds.

PDK

Nominal	Fast	Slow
1.5Fum ² 2 Mm Cap	c_mim15rf	
1.0Fum ² 2 Mm Cap	c_mimrf	
1.2v HS NFETs	nche,ncherf	
1.2v Std. NFETs	nch,ncherf	
1.2v HS PFETs	pche,pcherf	
1.2v Std. PFETs	pch,pcherf	
3.3v HS NFETs	rh3nes,rh3nerf (N/A)	
3.3v HS PFETs	rh3pes,rh3perf (N/A)	
Single-ended Inductors	ind_3p3,ind_0p9_stack (N/A)	
Diff Inductors	inddiff_3p3,inddiff_0p9_stack (N/A)	
1.2v Mosvar	vn_rf	
3.3v Mosvar	vmhh3rf	
VPMF	ppp3_10 (N/A)	
Unsalicided resistors	rmp,rsp,pwr,msp,nw (520-550 Ohm/Sq)	
N-Salicided resistors	rsm,rsn,pwr,rsn,nw (15 Ohm/Sq)	
P-Salicided resistors	rsp,rsp,pwr,rsn,nw (20 Ohm/Sq)	

PVT

Transistor (PDK)

nchrf,ncherf,pchrf,pcherf
w>=0.73um, L>= 60 nm, nb>=4

NMOS

PMOS

Resistor (PDK)

Unsalicided resistors (rmp,rsp,pwr,msp,nw)
w>=0.5um, L>=2.0um
(520-550 Ohm/Sq) depending aspect ratio

N-Salicided resistors (rsm,rsn,pwr,rsn,nw)
w>=0.5um, L>=3.0um
(15 Ohm/Sq)

P-Salicided resistors (rsp,rsp,pwr,rsn,nw)
w>=0.5um, L>=3.0um
(20 Ohm/Sq)

R

Varactor (PDK)

vn_rf
0.65um <= (wg,lg) <= 103um (Design Rule)
wg>=2um, lg>=0.1um, nb>=15 (Layout PDK)

vmhh3rf, vpph3rf
wg>=2um, lg>=0.35um, nb>=15 (Layout PDK)

MIM

MIM Capacitor (PDK)

c_mimrf
1.0um <= (WL) <= 103um (Design Rule)
W=4um, L=17um (Layout PDK)

c_mim15rf cannot be used.

c_mim is only for parasitic, no resistance, no inductance.

MIM

Varactor

MOS cap

model

Capacitor (model)

MIM TL (model)

MIM TL

Transmission Line (model)

TL with L/T

RF PAD (model)

60um x 40um RF PAD

RF PAD

DC probe (meas.)

only reliable up to 20GHz

DC probe

for ADS

Each component is implemented as an in-house PDK for Agilent ADS.

Nov.12. 2015.

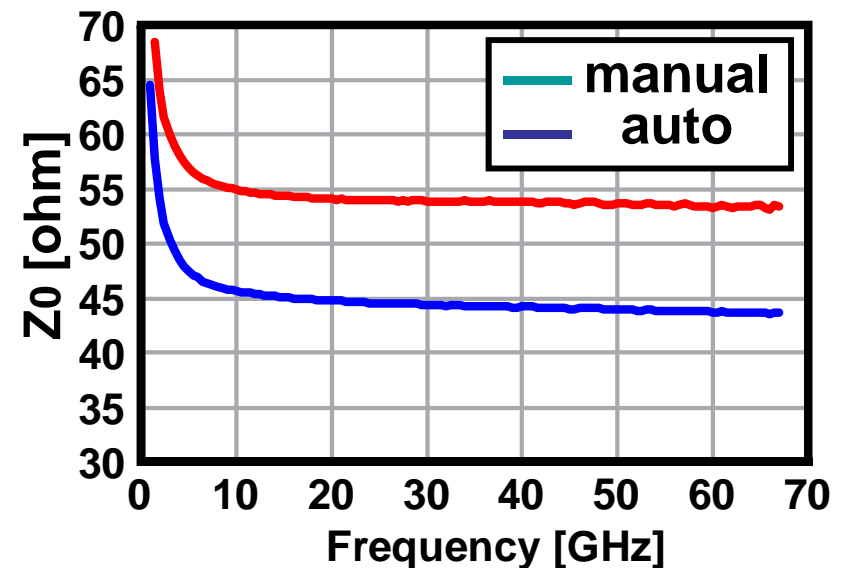
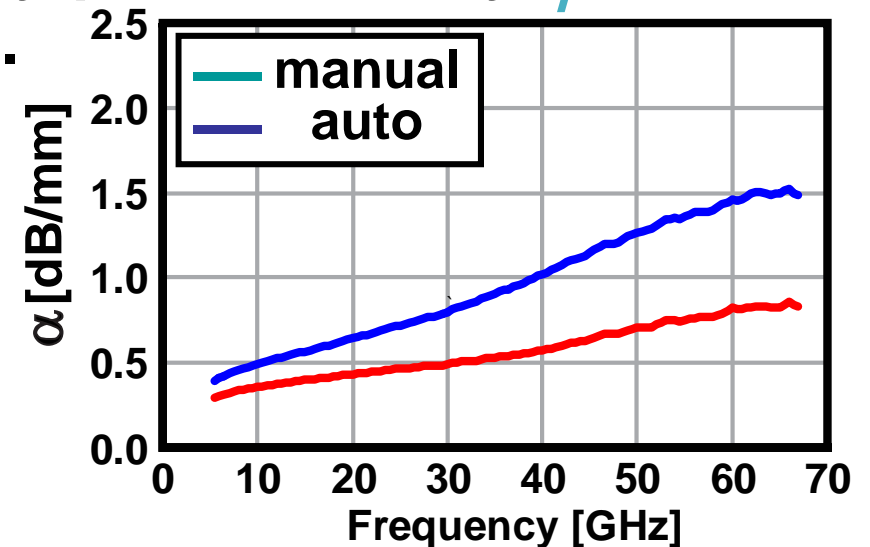
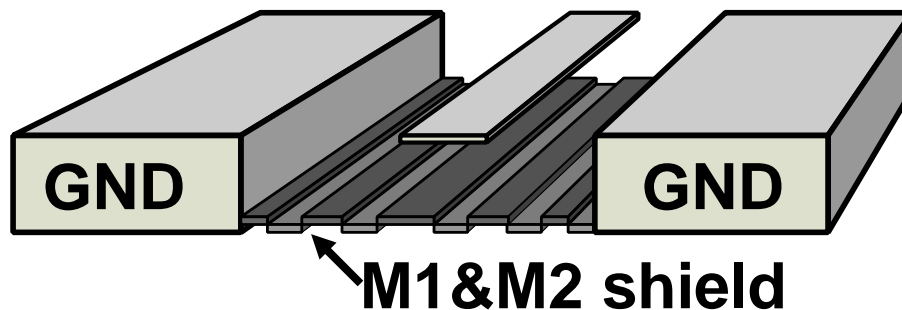
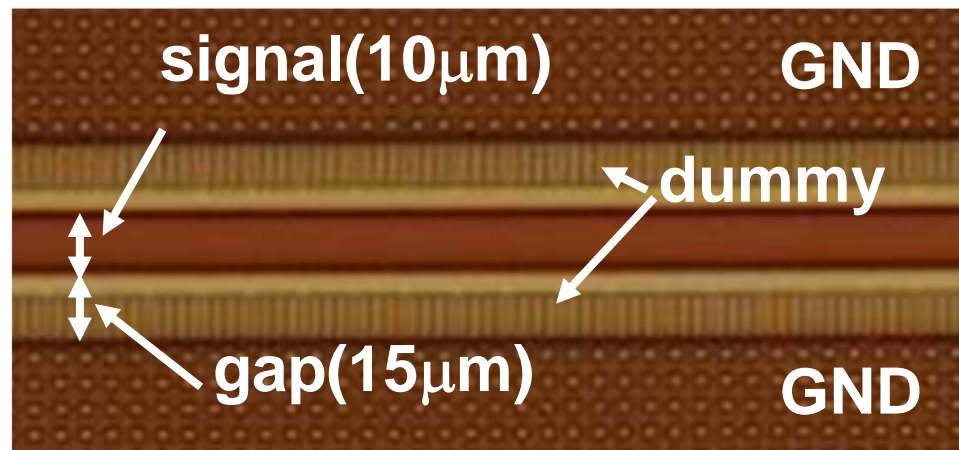
Matsuzawa & Okada Lab.

Key technology: low loss TR line

38

Optimized parameter and manually-placed dummy metal realize low loss transmission line.

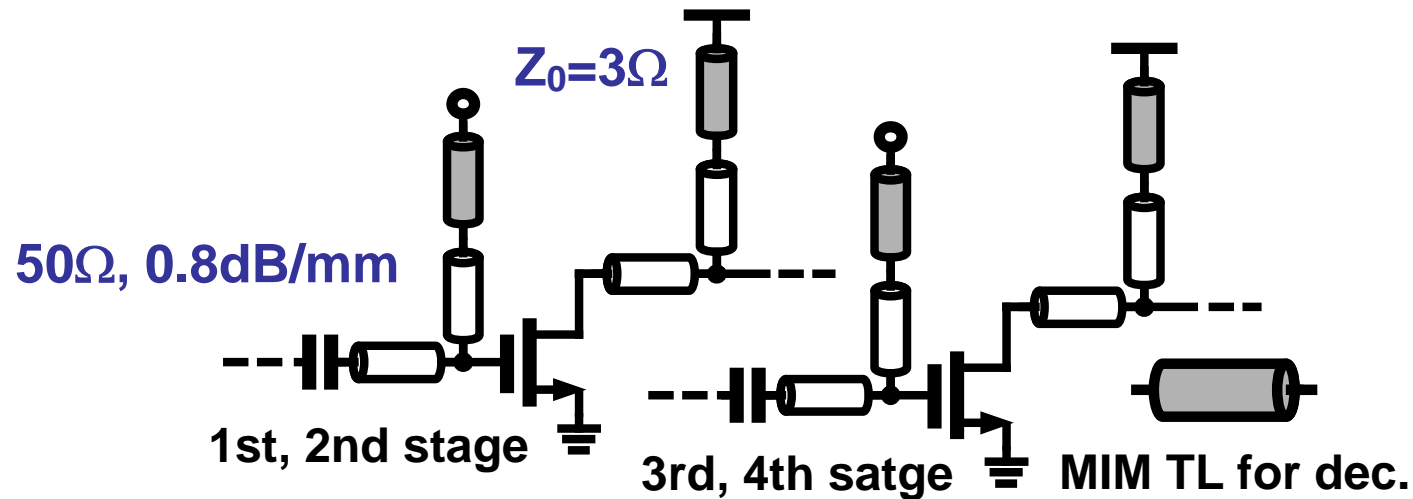
- 0.8dB/mm
- Manually-placed dummy metal



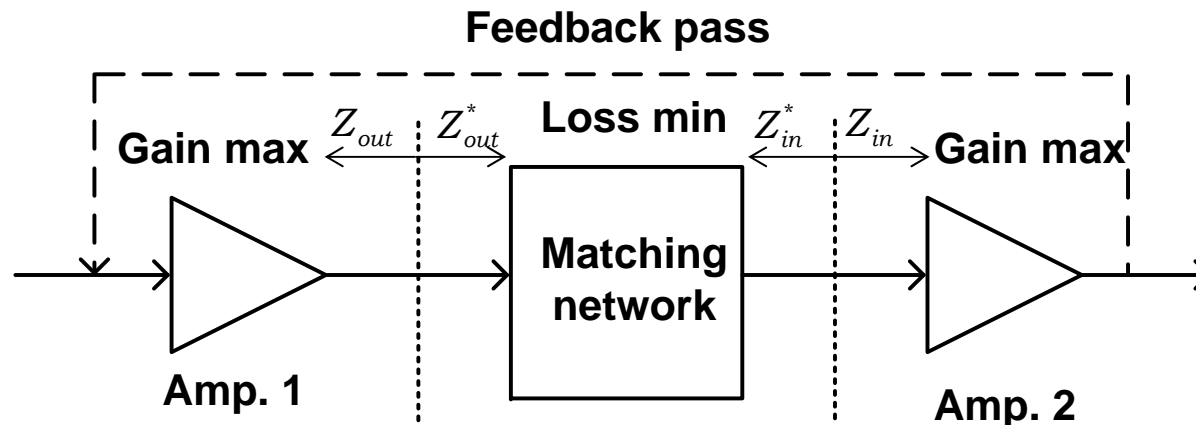
Basic amplifier design

39

Amplifier design;
accurate sizing, biasing, impedance matching and decoupling.



A several GHz oscillation will occur, if the feedback passes are made.

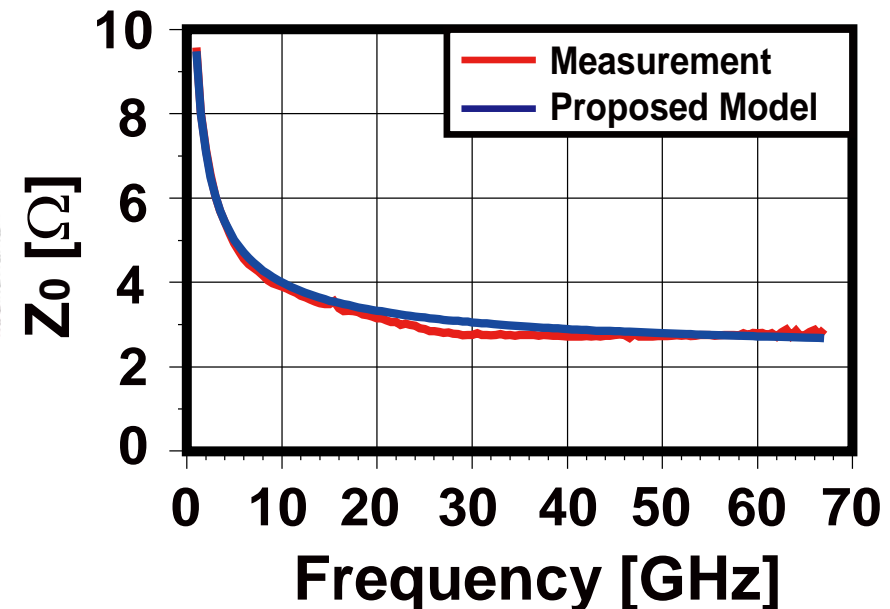
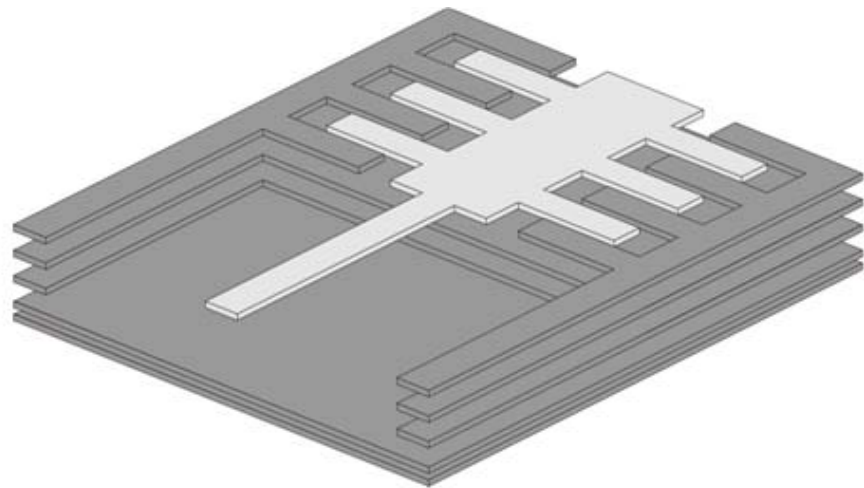


Decoupling capacitor

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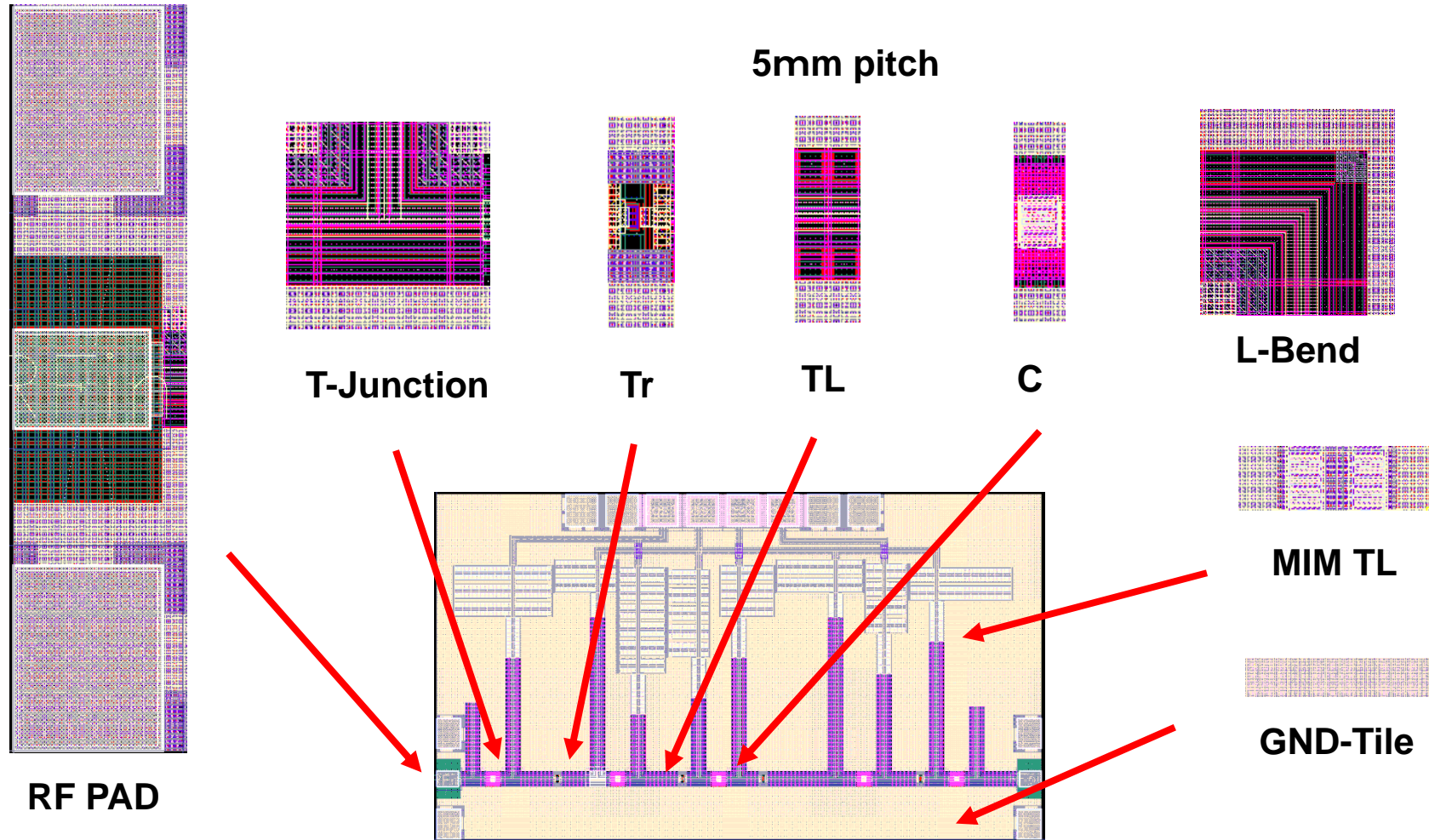
A decoupling capacitor has been developed using MIM capacitor with distributed structure to prevent a resonance, Which occurs, if used a conventional capacitor structure. A very low impedance of 3 ohm is realized.



Tile-based layout method

41

Each component is previously measured and modeled.
The same layout is utilized to maintain modeling accuracy.



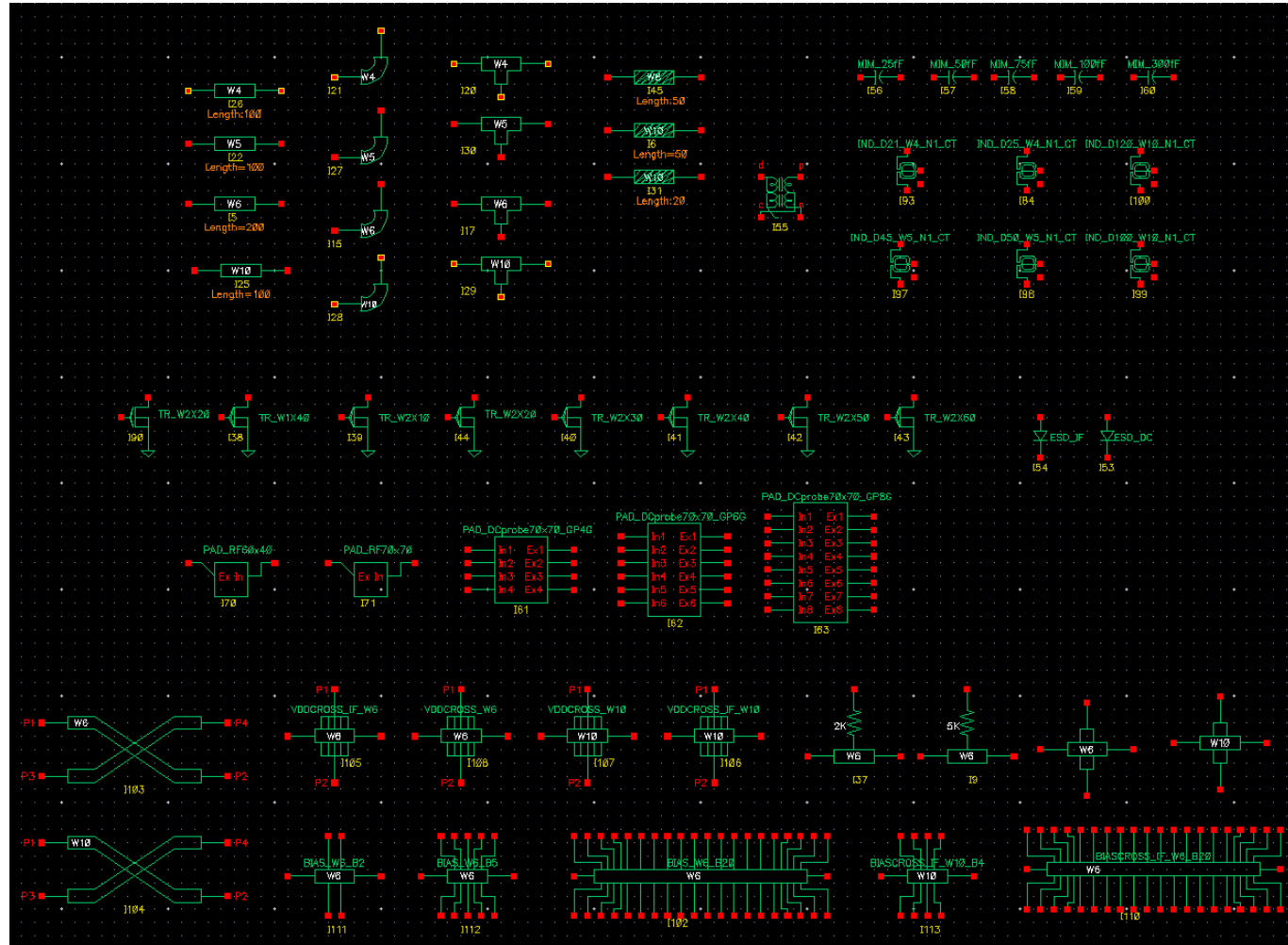
In-house PDK

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We have developed in-house PDK for 60-GHz circuit design

for Virtuoso

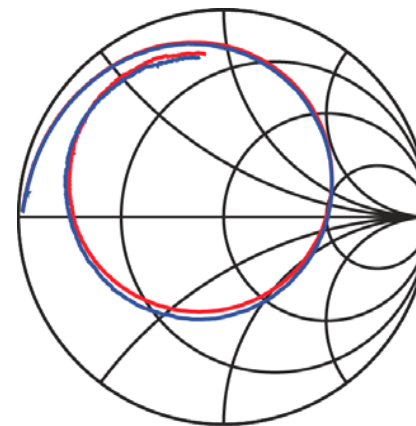
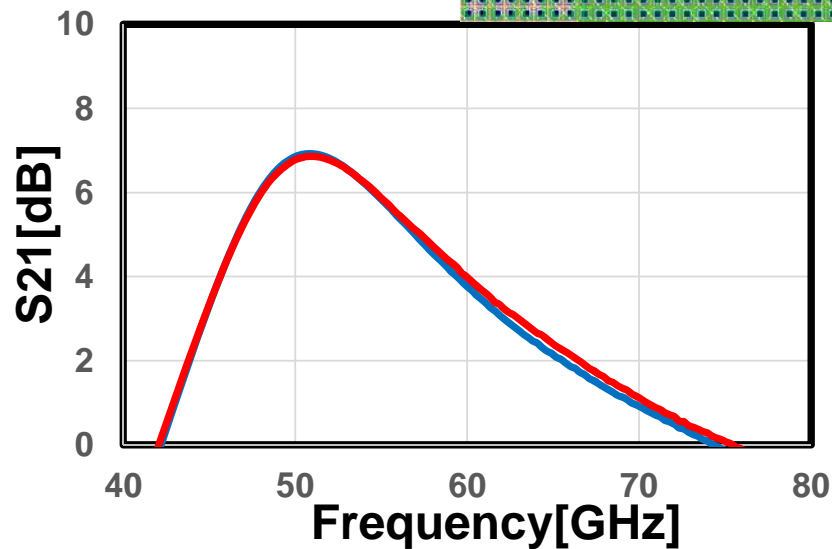
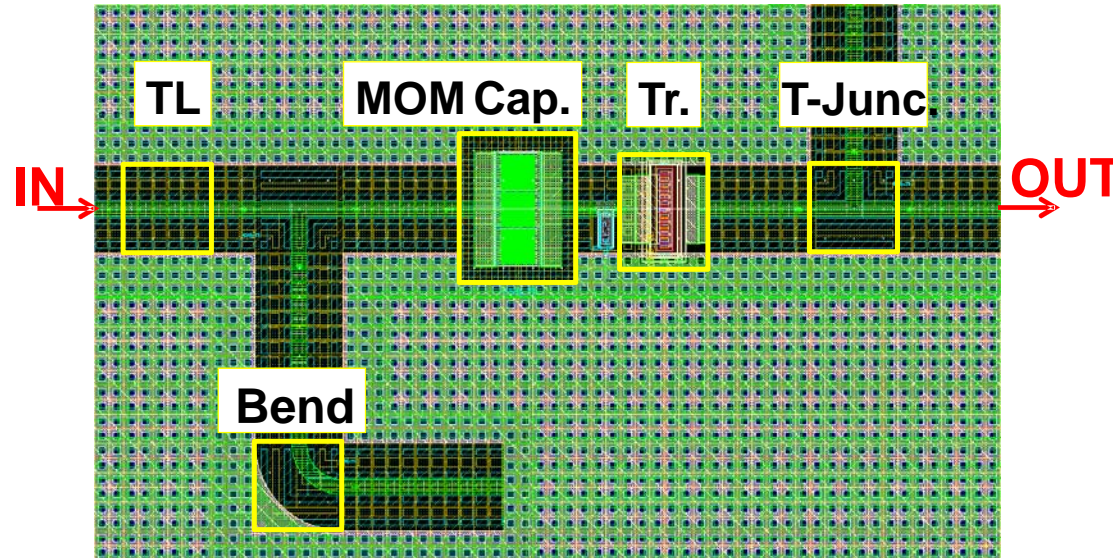


Nov.12. 2015.

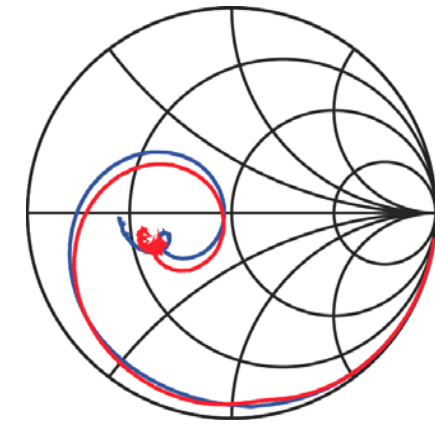
Design Example

43

High design accuracy at around 60GHz has been attained



S11
(RED:meas BLUE:sim)



S22

High Speed and Low Power ADC

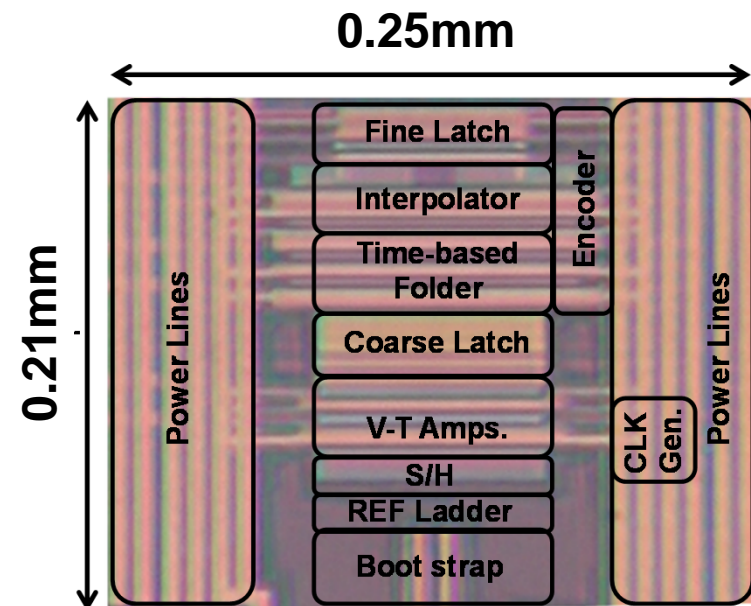
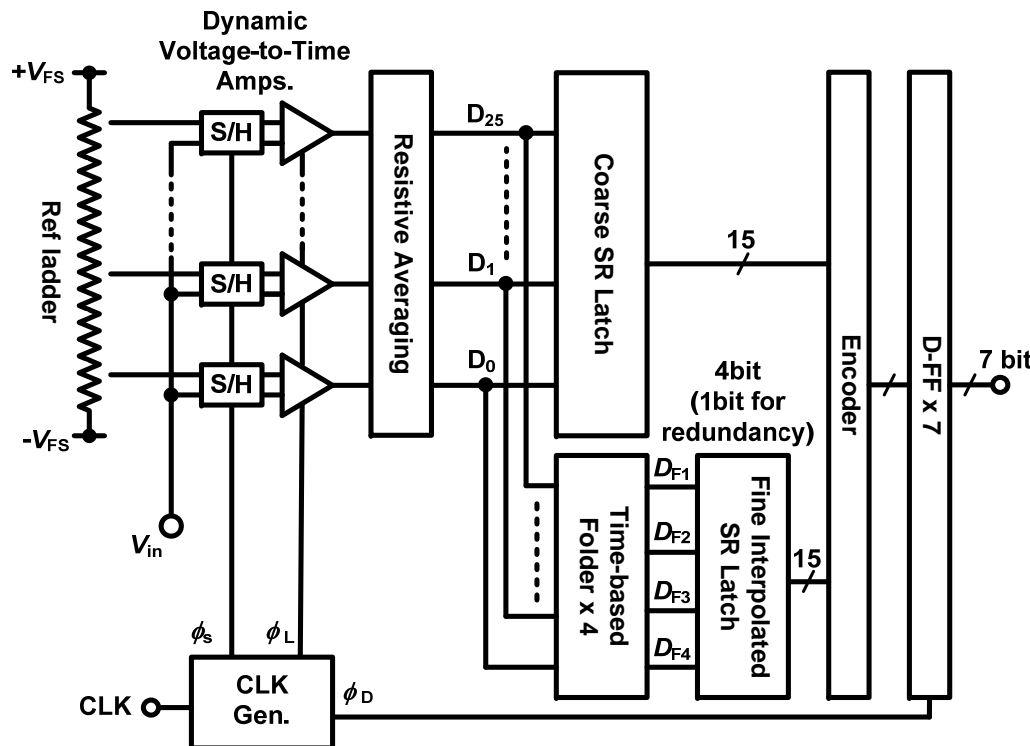
7bit 2.2GSps ADC for 60GHz ABB

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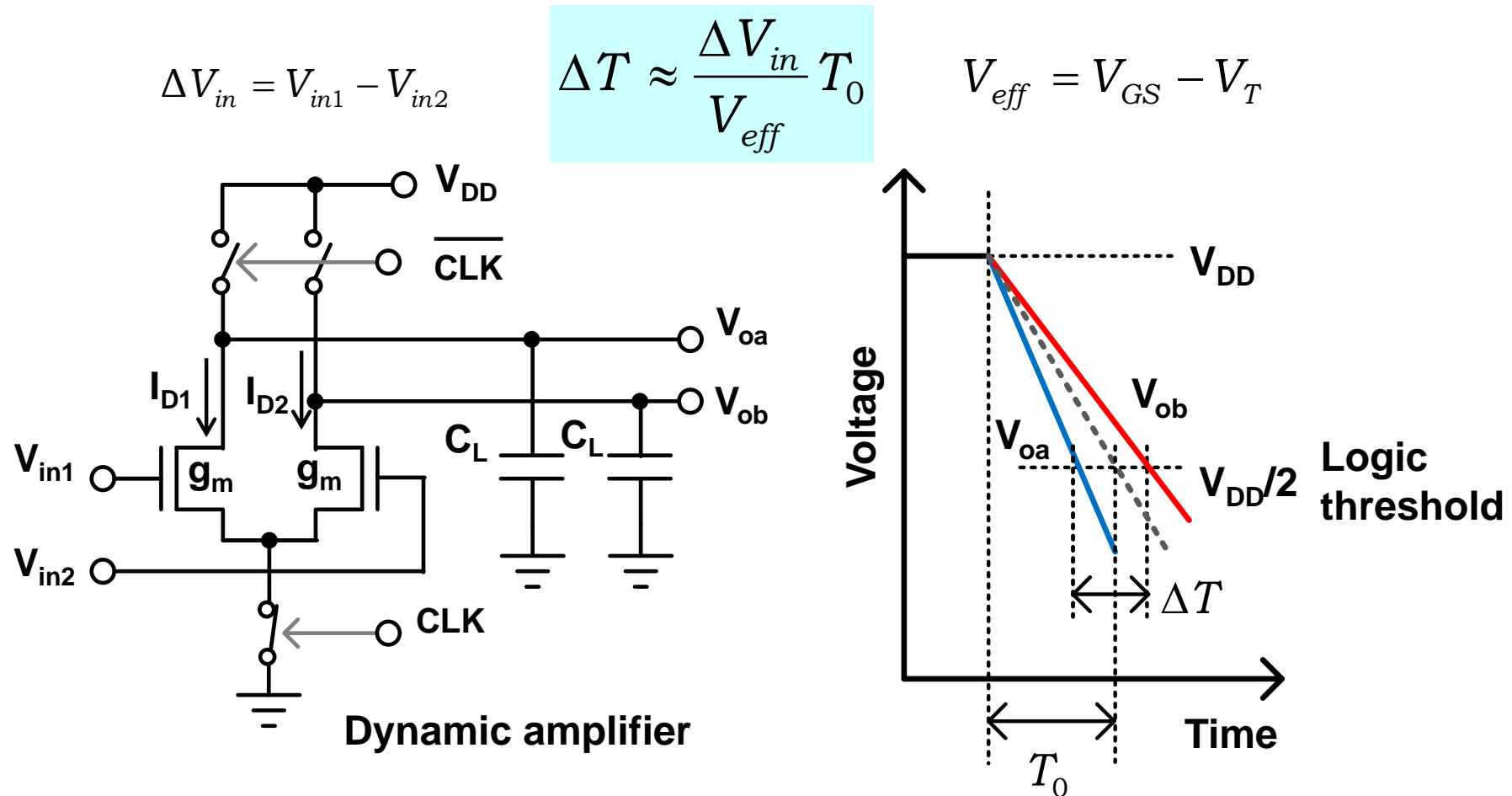
- 7bit ADC for the 16QAM modulation
- Convert the voltage difference to the timing difference
- Folding and interpolation are realized by logic gates

M. Miyahara, A. Matsuzawa, ISSCC 2014



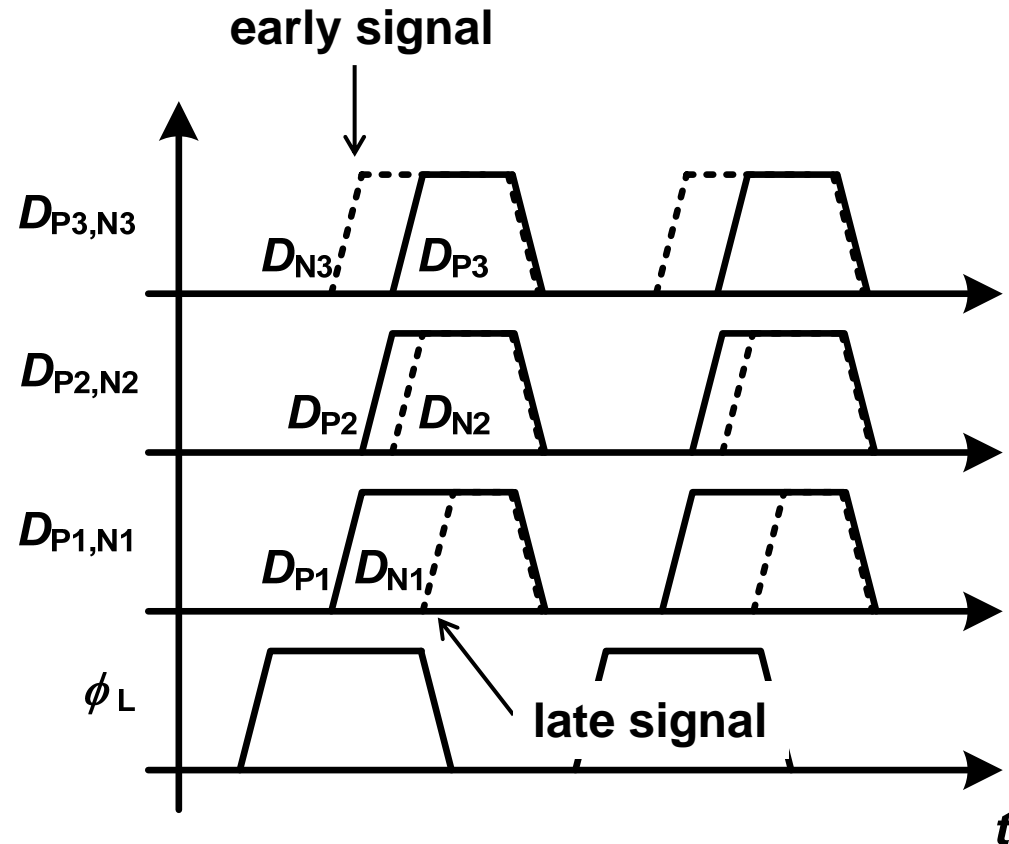
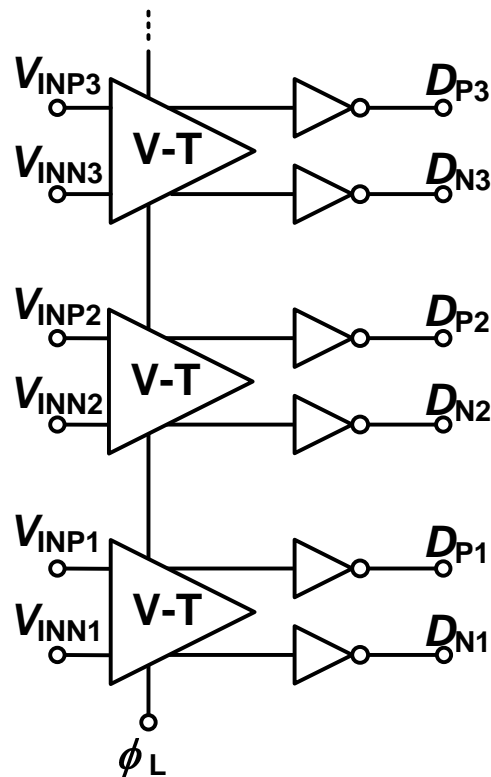
V to T conversion in dynamic amplifier / 46

Voltage difference can be converted to time difference in a dynamic amplifier.



Conversion from the voltage to the timing / 47

The signal generation of larger voltage difference is faster in the dynamic amplifier.

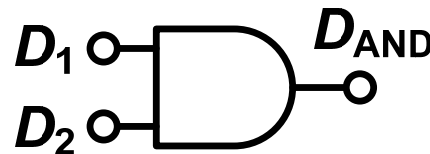


Dynamic Amps.

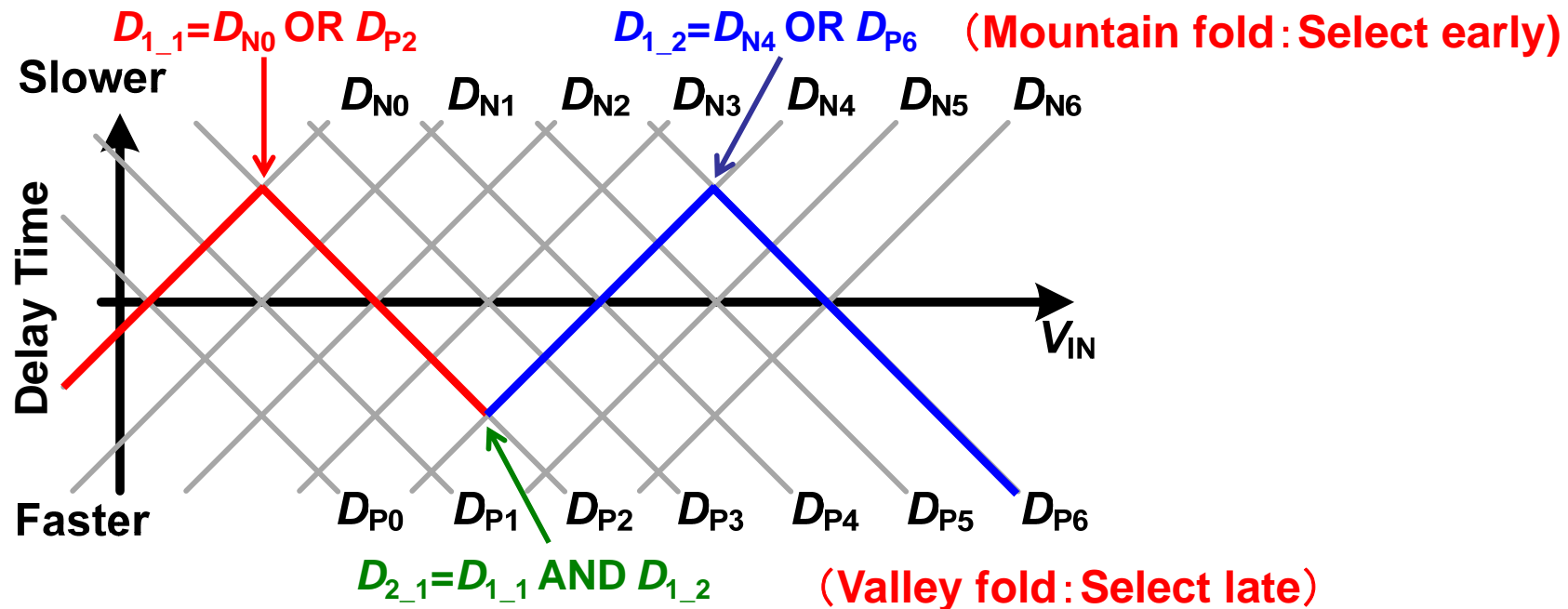
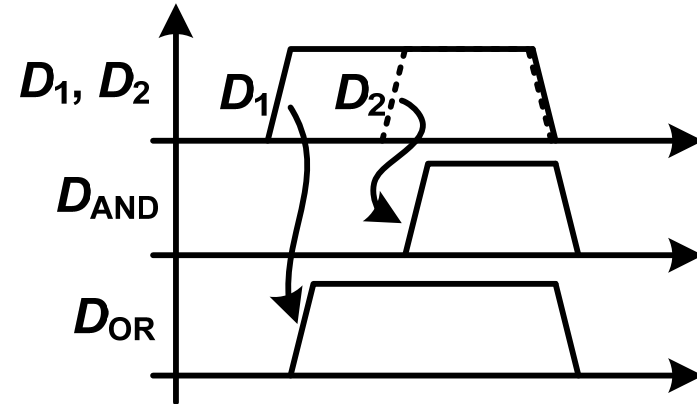
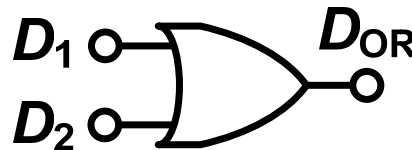
Signal folding in time-domain

Signal folding in time-domain can be realized easily by simple logic gates.

AND: Select late pulse



OR: Select early pulse



Performance comparison

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Highest SNDR of 37.4 dB is attained in flash ADCs

No calibration circuits are required.

This ADC will contribute increase of data rate of 60 GHz transceivers.

P_d is large so far, however can be reduced by the optimization.

	ISSCC 2008 [3]	VLSI 2012 [8]	VLSI 2013 [9]	This work
Technology	90nm	40nm	32nm SOI	40nm LP
Resolution [bit]	5	6	6	7
Power Supply [V]	1	1.1	0.85	1.1
Sampling Frequency [GS/s]	1.75	3	5	2.2
Power Consumption [mW]	2.2	11	8.5	27.4
SNDR @Nyquist [dB]	27.6	33.1	30.9	37.4
FoMw [fJ/conv.-step]	64.5	99.3	59.4	210
FoMs [dB]	143.5	144.4	145.6	143.3
Core area [mm ²]	0.0165	0.021	0.02	0.052
Calibration	Off chip	Foreground	Off chip	No need

Future Prospect of High Data Rate Wireless Systems

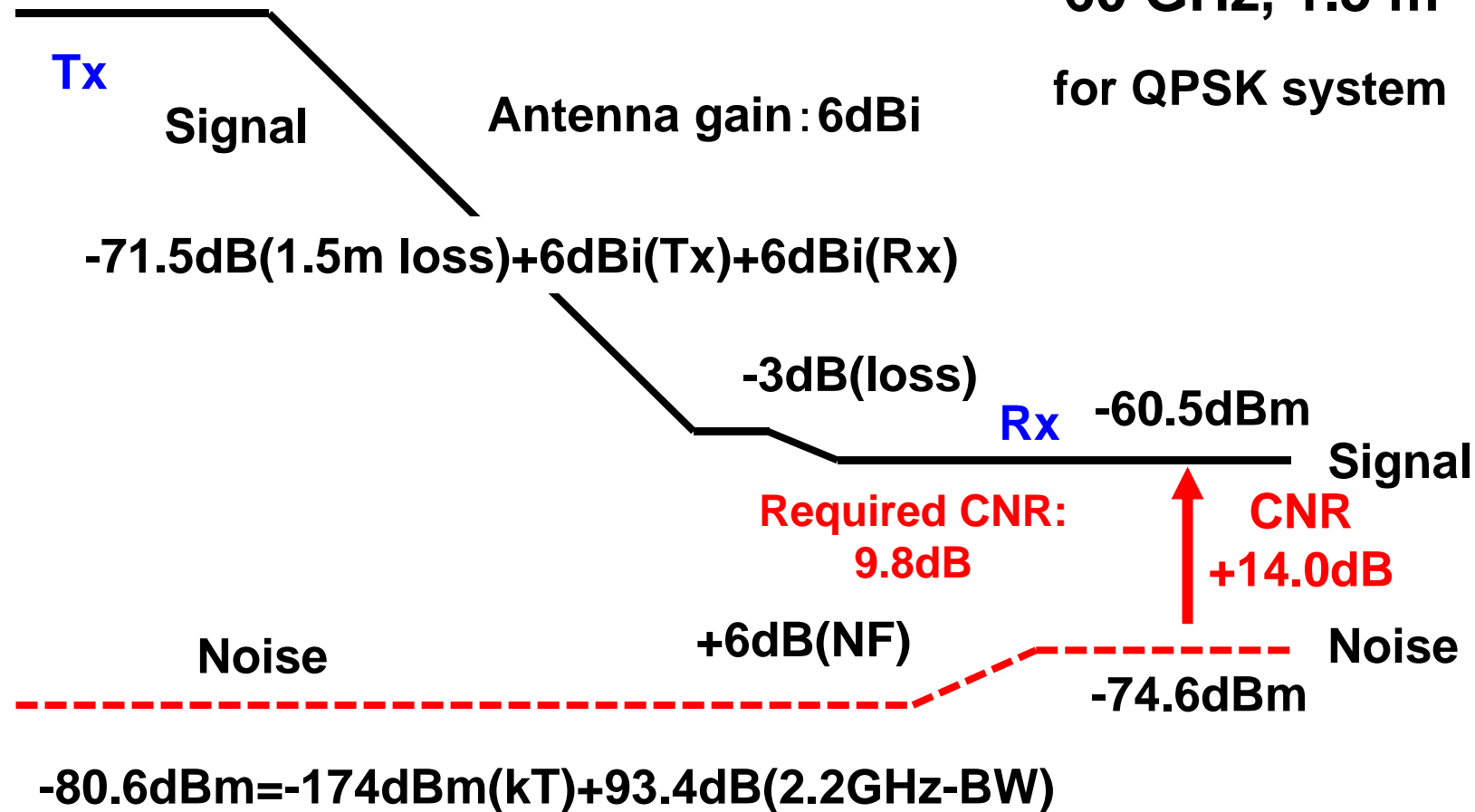
Link budget example of wireless system / 51

Transmitted RF power is lowered so much at the receiver

$$6\text{dBm}(P_{\text{out}}) - 4\text{dB}(\text{back-off}) = 2\text{dBm}$$

60 GHz, 1.5 m

for QPSK system



Calculate the data rate as function of carrier frequency and Tx power

Shannon's theory $D_{rate} = BW \log_2 \left(1 + \frac{S}{N} \right)$

$$D_{rate} \approx BW \frac{\log_{10}(SNR)}{0.3} = BW \frac{SNR(dB)}{3}$$

Received signal $P_{RX} (dB) = P_{TX} - B_{OFF} + G_{AT} + G_{AR} - I_L - S_{LOSS}$

Spatial loss $S_{LOSS} = -20 \log \left(\frac{\lambda}{4\pi d} \right) = -20 \log \left(\frac{c}{4\pi d f_c} \right) = 20 \log \left(\frac{4\pi}{c} d f_c \right)$

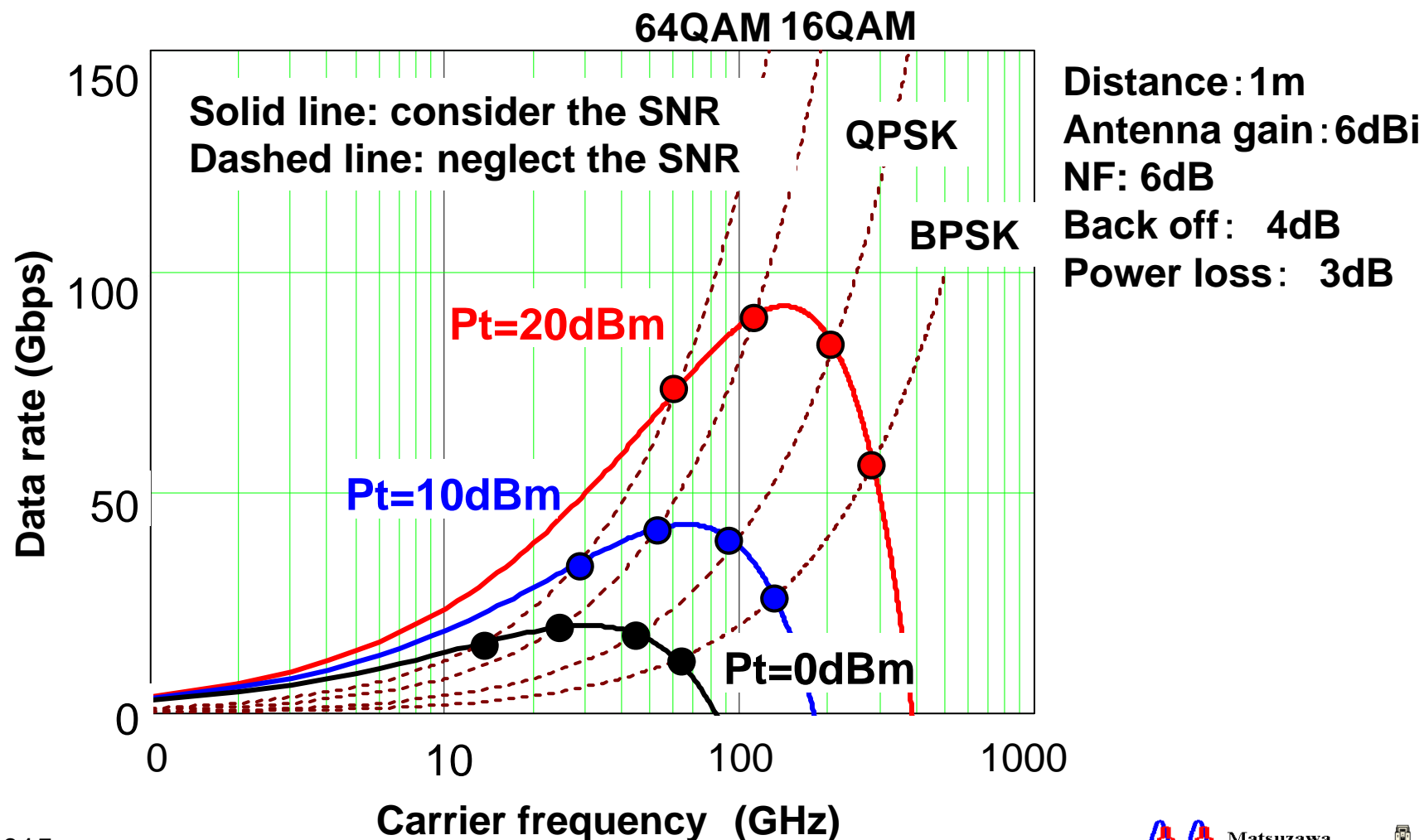
d: distance

f_c: carrier frequency

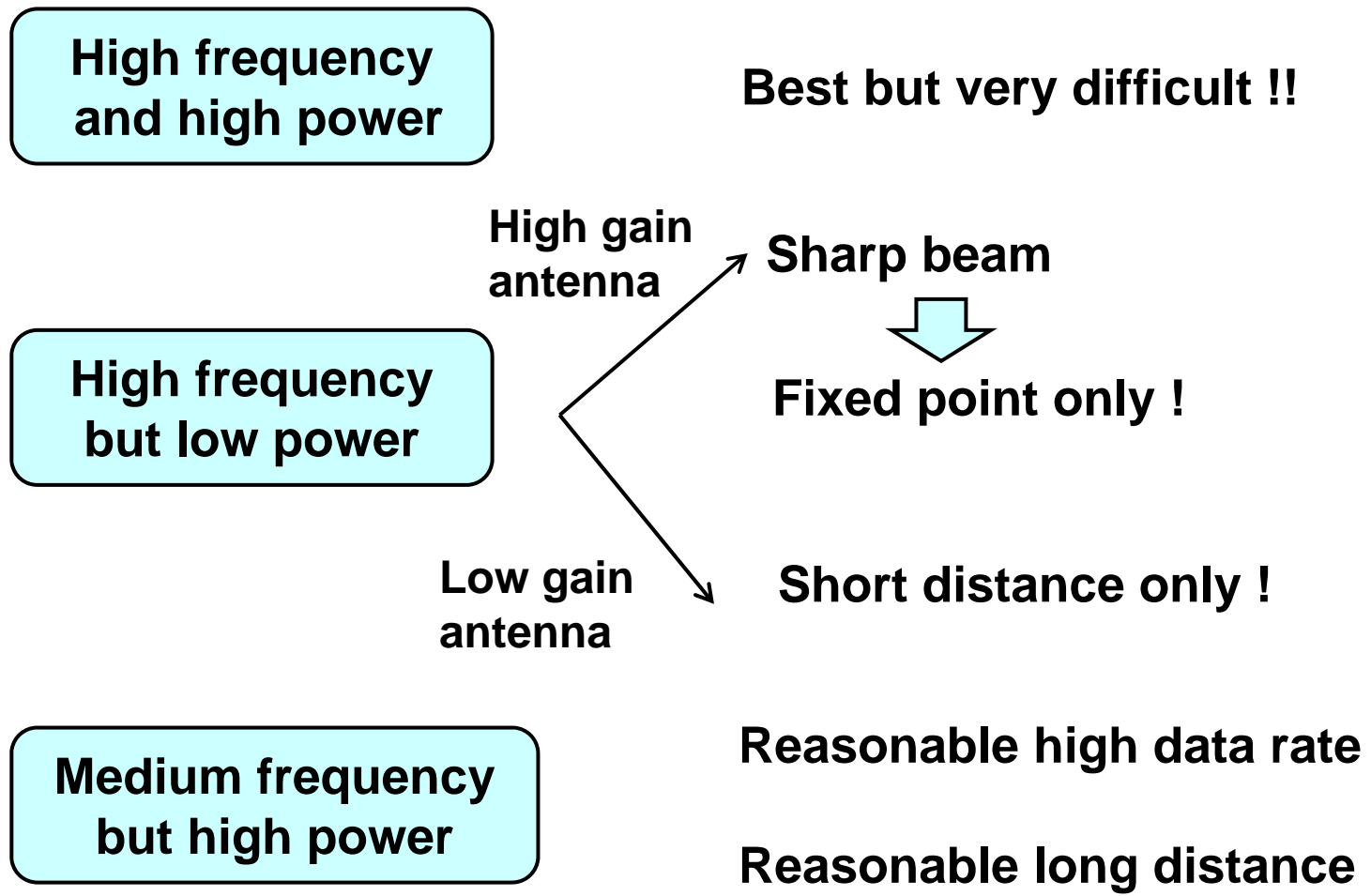
Noise $P_n (dBm) = -174 + 10 \log BW + NF$

Estimated data rate

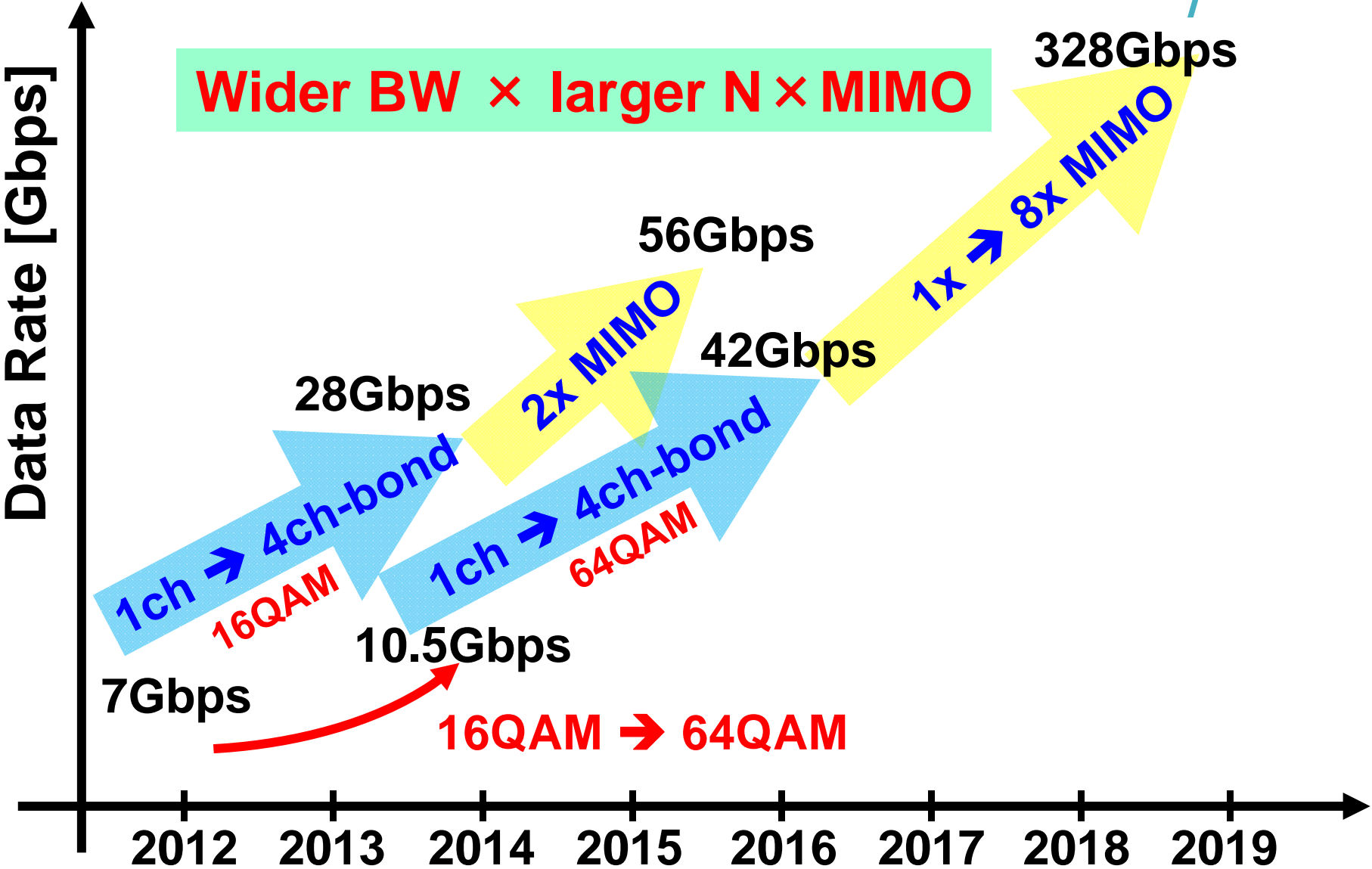
There is an optimum frequency for the maximum data rate.
Higher Tx power is required to increase the data rate.
16 QAM looks the best to attain the maximum data rate.



Future direction should be chosen by the usage model



Our roadmap for 300Gbps data transfer / 55



- High data rate wireless communication is demanded
- 28 Gb/s has been realized
- Wider bandwidth and higher SNR are the keys
 - Multi-cascaded amplifier
 - Passive mixer with resistive feedback
 - Injection locked I/Q oscillator
 - 7 bit ADC with time domain processing
- Accurate RF modeling and measurement up to 100 GHz is fundamentally important
- Optimum frequency for the maximum data rate.
 - Higher frequency does not guarantee the higher data rate
 - Higher Tx power is required to increase the data rate.
- Future direction should be chosen by the usage model
 - Long distance with reasonable data rate
 - Short distance with high data rate

$$D_{rate} = BW \log_2 \left(1 + \frac{S}{N} \right)$$

- I would like to thank Prof. K. Okada and this work was partially supported by MIC, SCOPE, MEXT, STARC, Huawei, Canon Foundation, STAR, and VDEC in collaboration with Cadence Design Systems, Inc., Synopsys, Inc., and Mentor Graphics, Inc., and Agilent Technologies Japan, Ltd.

And also,

Acknowledgement

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Thanks lot to students

